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(54) **SEMICONDUCTOR DEVICE**

(57) **ABSTRACT**

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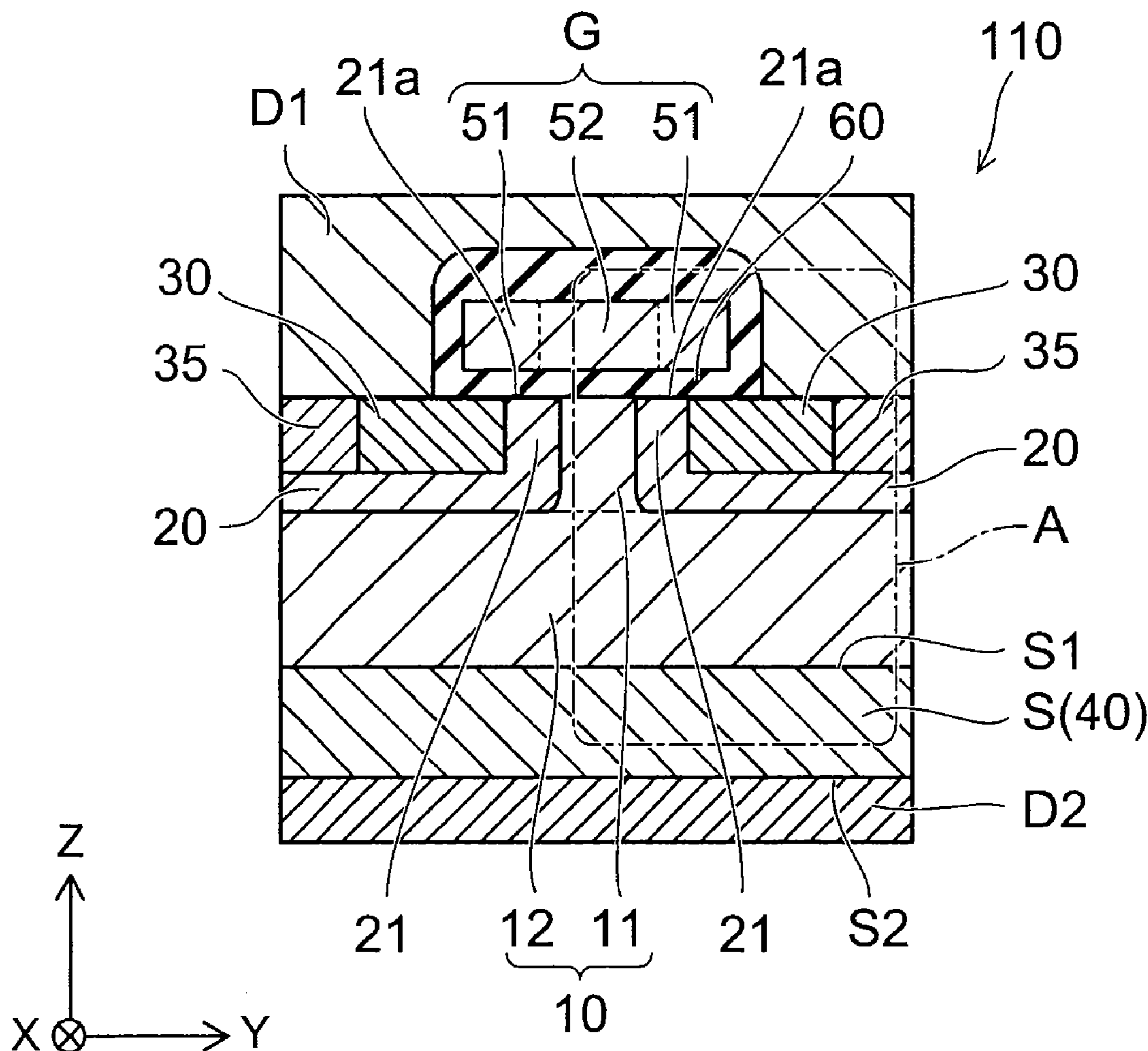
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According to one embodiment, a semiconductor device includes a first semiconductor region, a second semiconductor region, a third semiconductor region, an insulating film, and a control electrode. The first semiconductor region includes a silicon carbide of a first conductivity type. The second semiconductor region is provided on the first semiconductor region, includes a silicon carbide of a second conductivity type, and has a first main surface. The third semiconductor region is provided on the second semiconductor region and includes the silicon carbide of the first conductivity type. The film is provided on the surface. The electrode is provided on the film, and has a first region close to the third semiconductor region side, and a second region closer to the first semiconductor region side than the first region. An effective work function of the first region is larger than an effective work function of the second region.



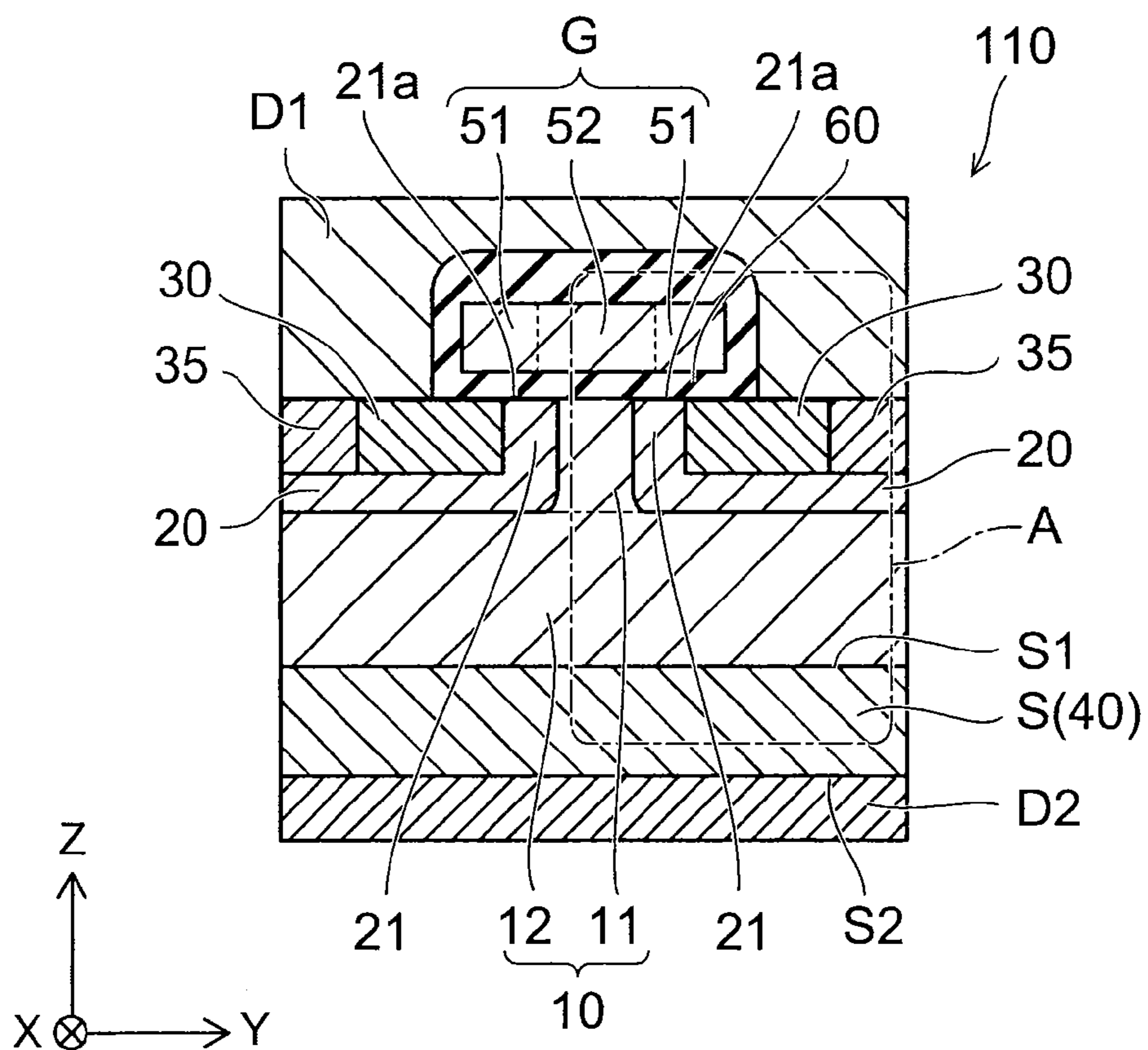


FIG. 1A

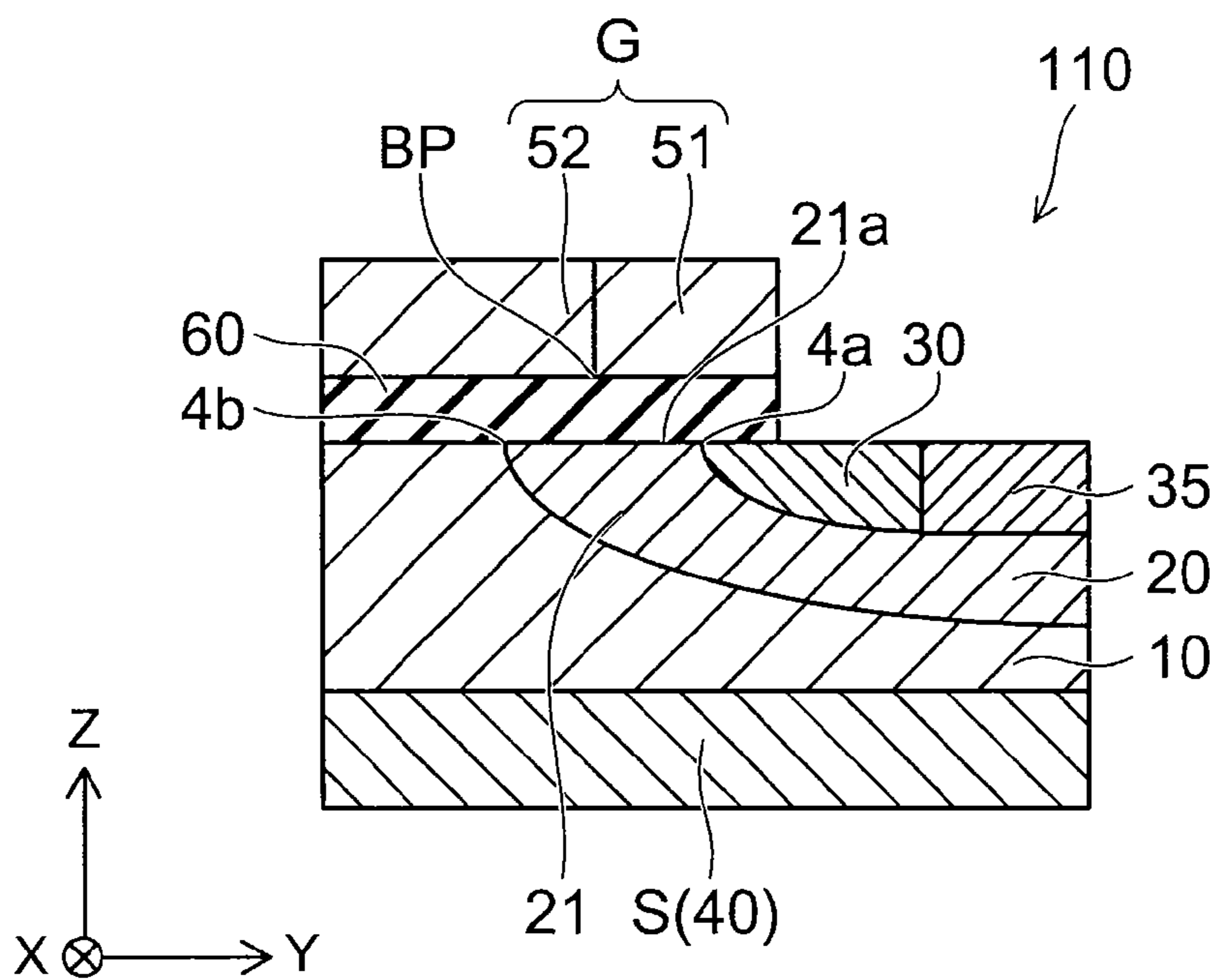


FIG. 1B

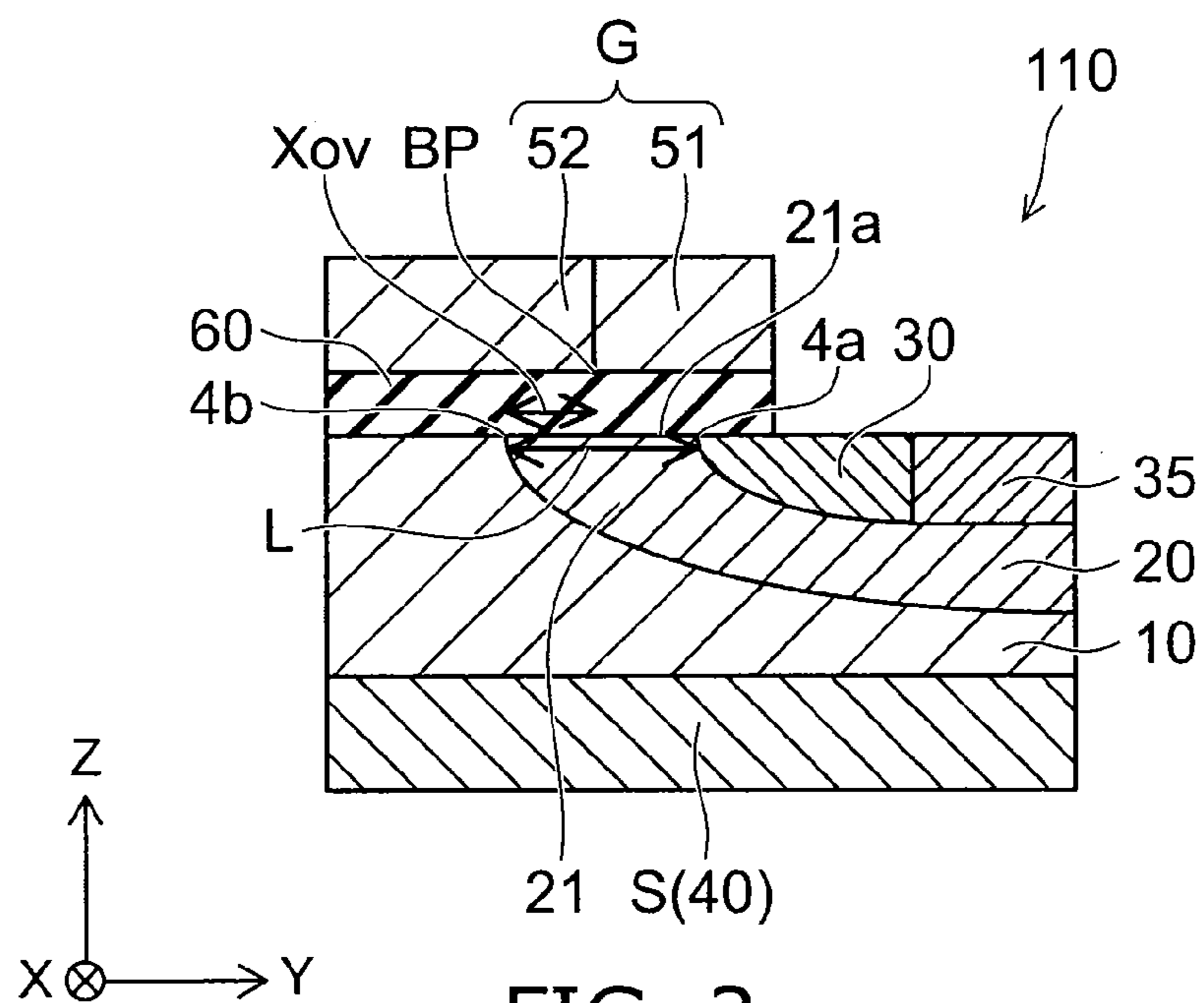


FIG. 2

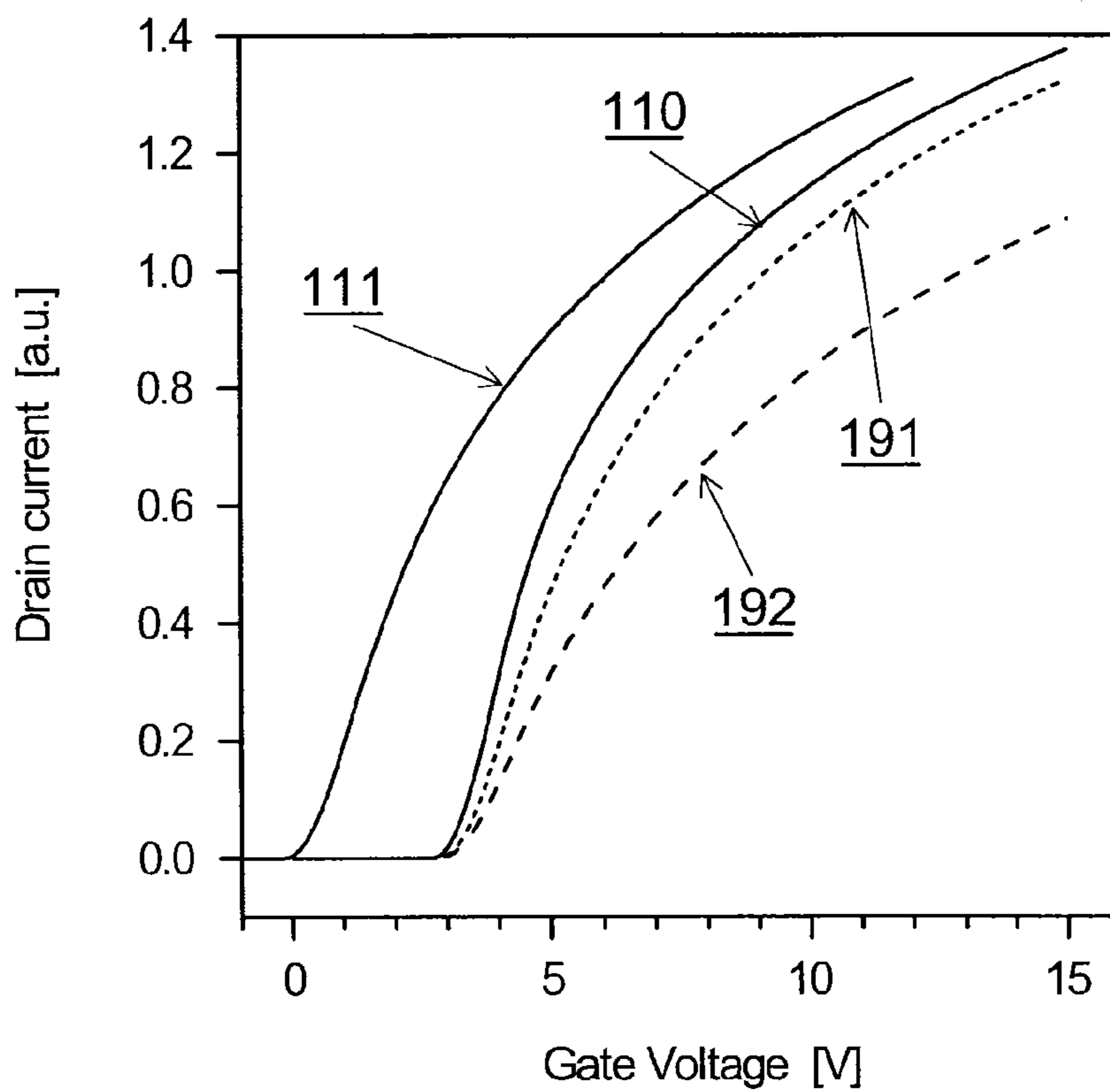


FIG. 3

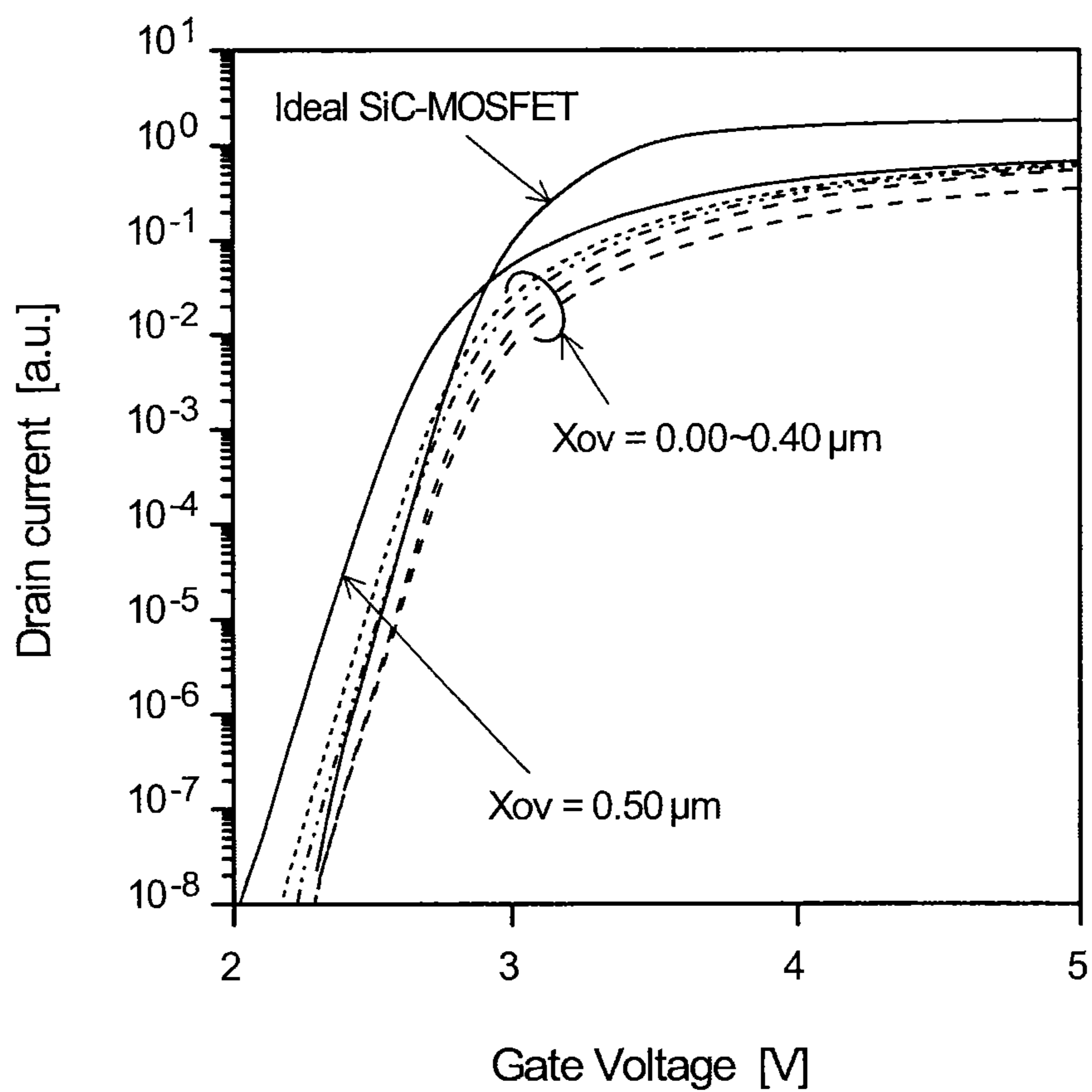


FIG. 4

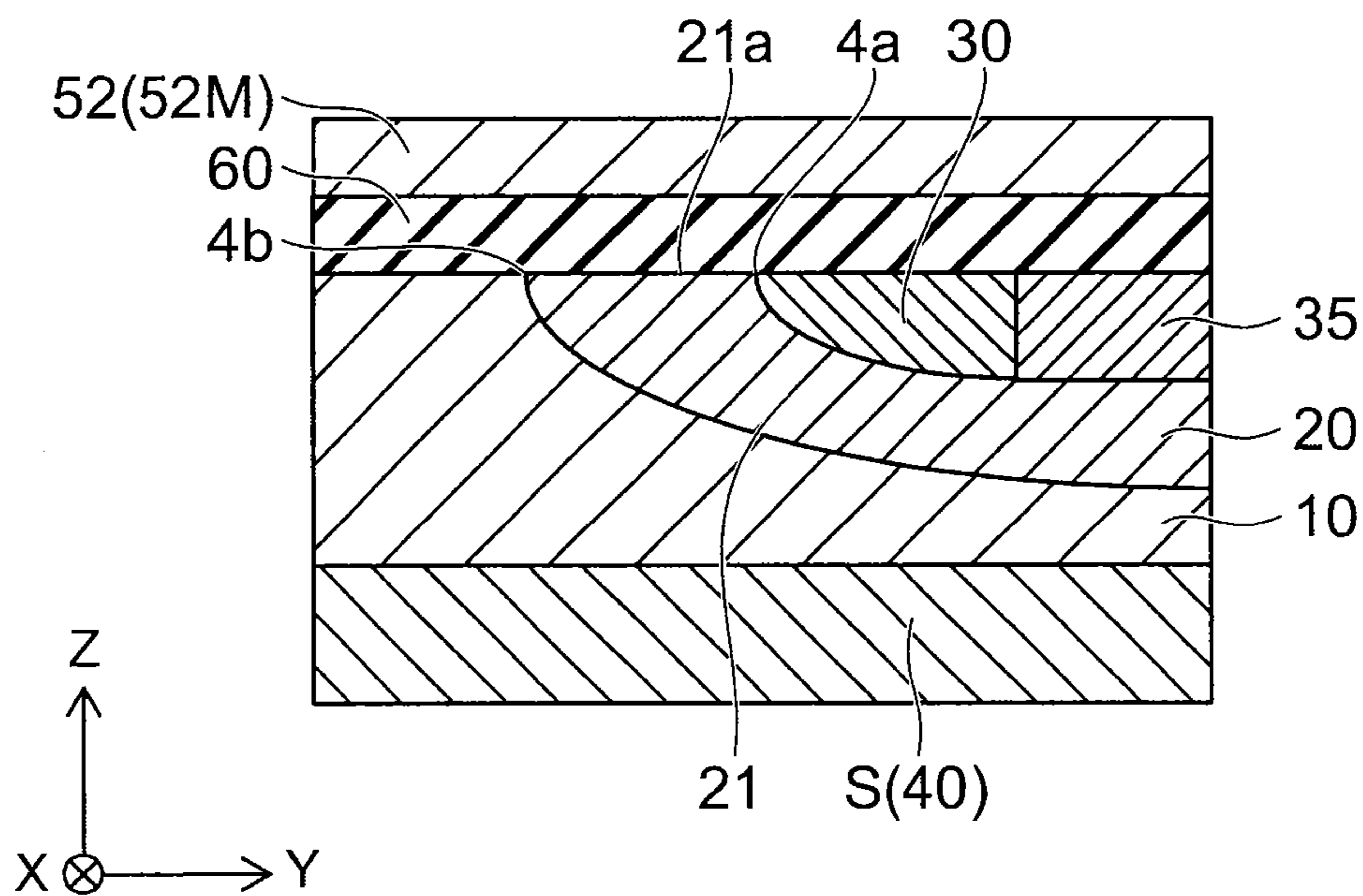


FIG. 6A

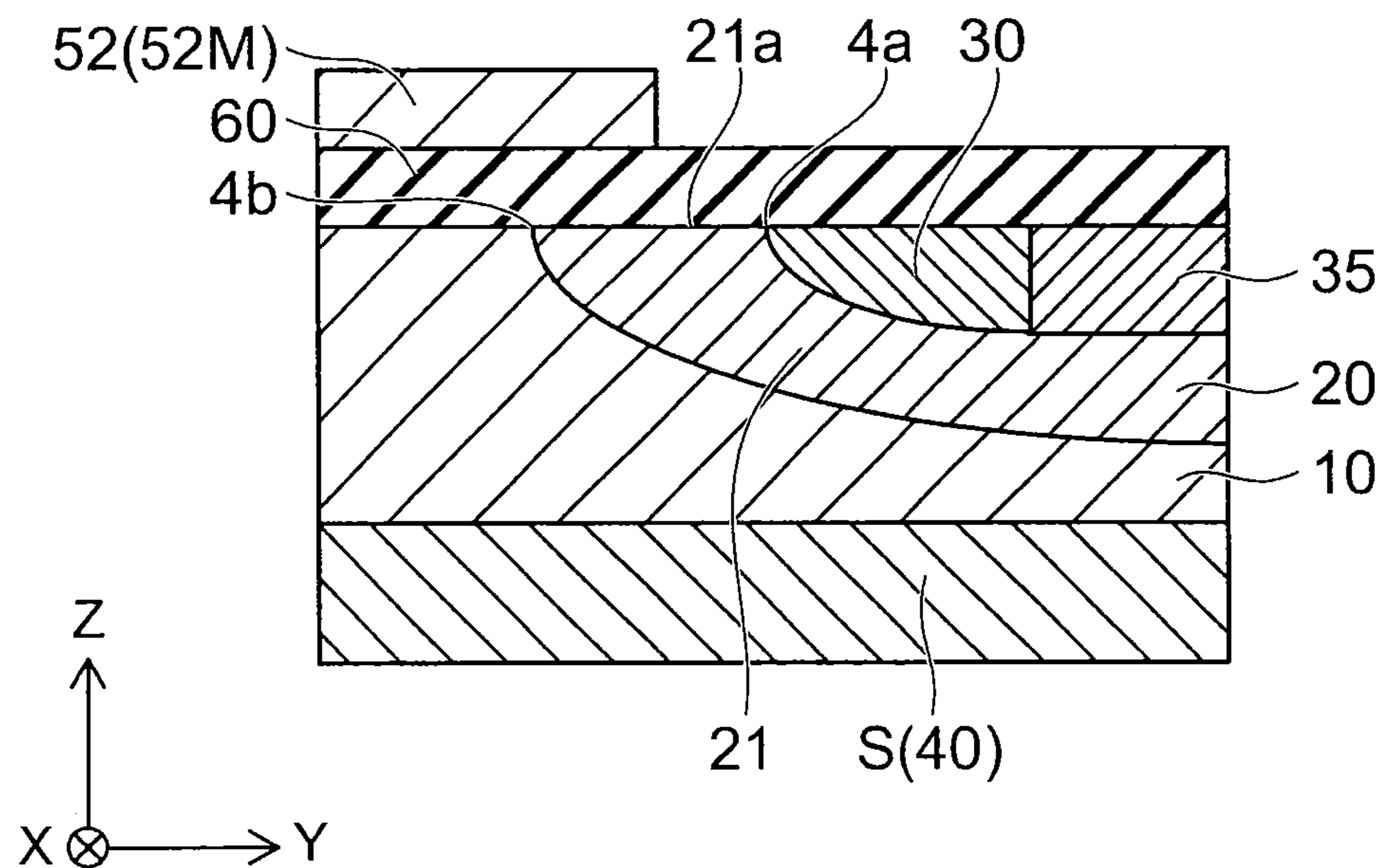


FIG. 6B

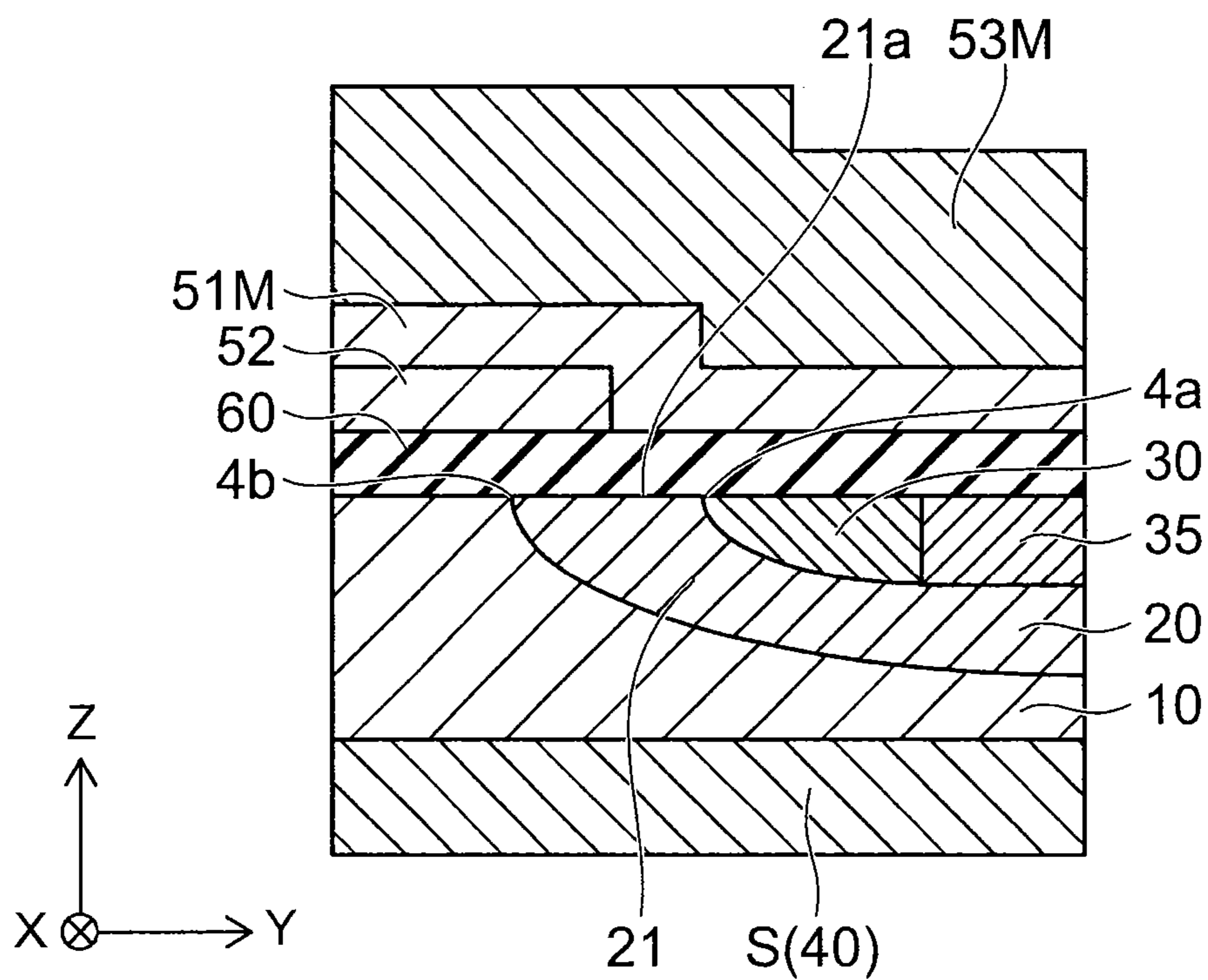


FIG. 7A

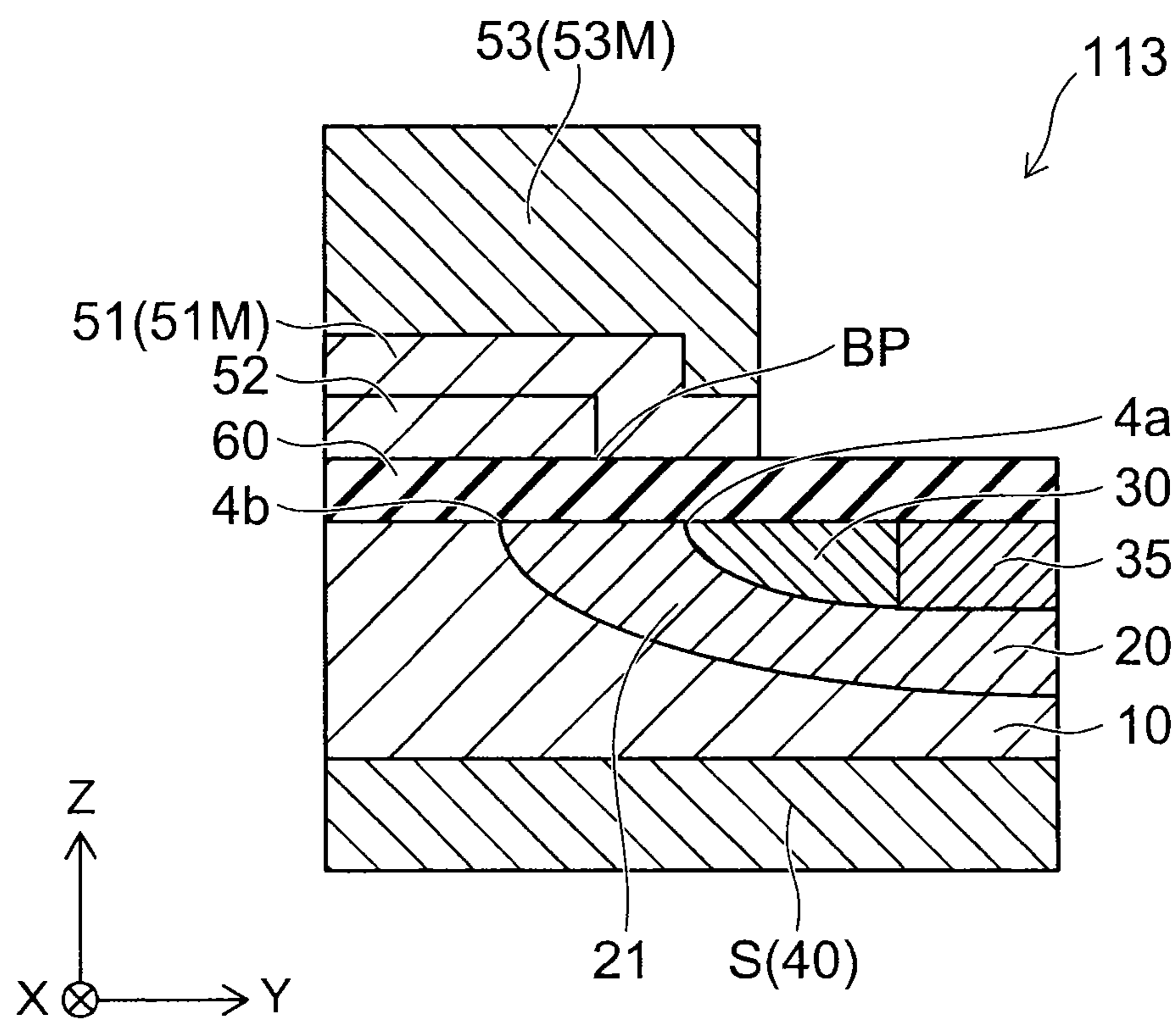


FIG. 7B

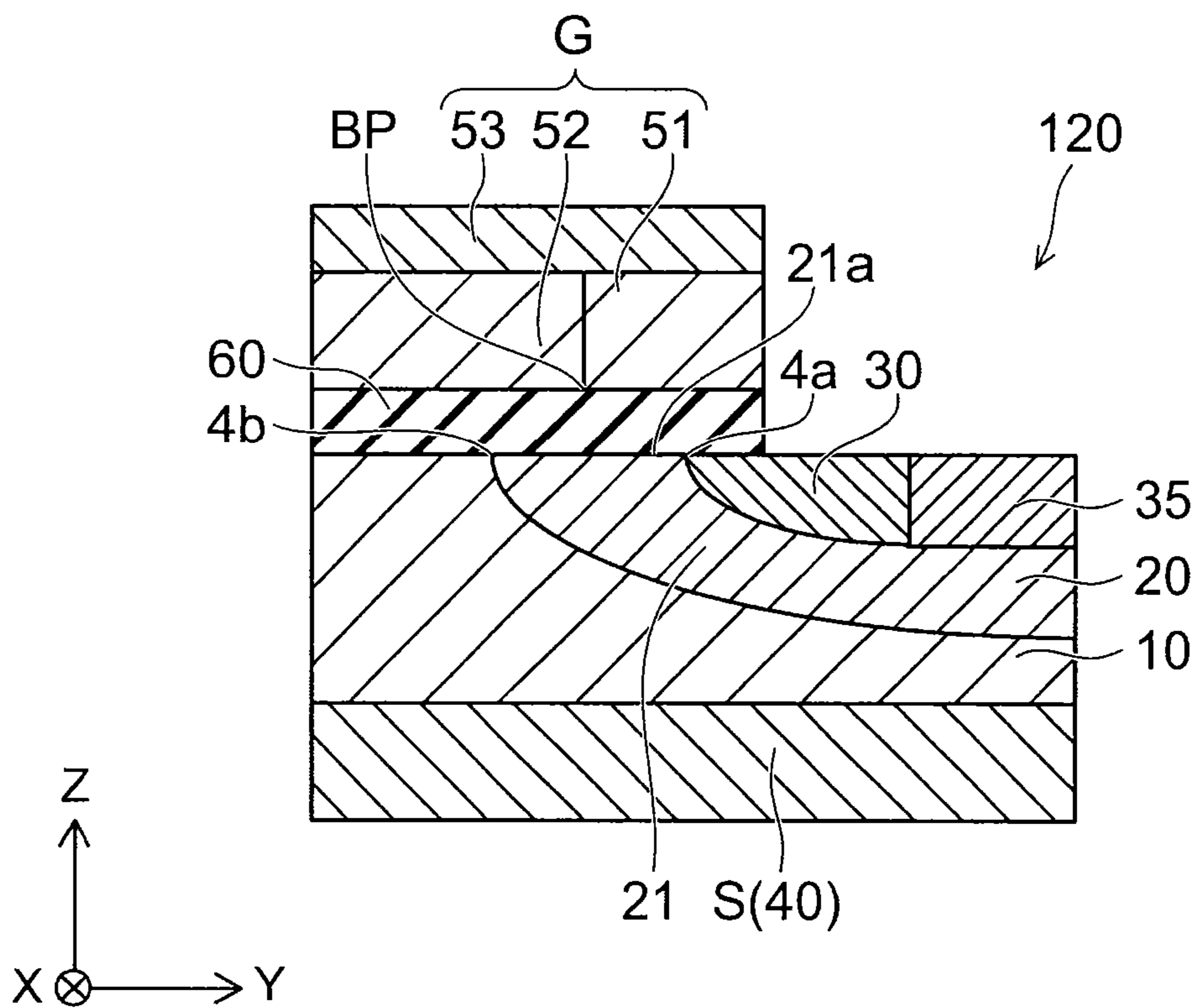


FIG. 8

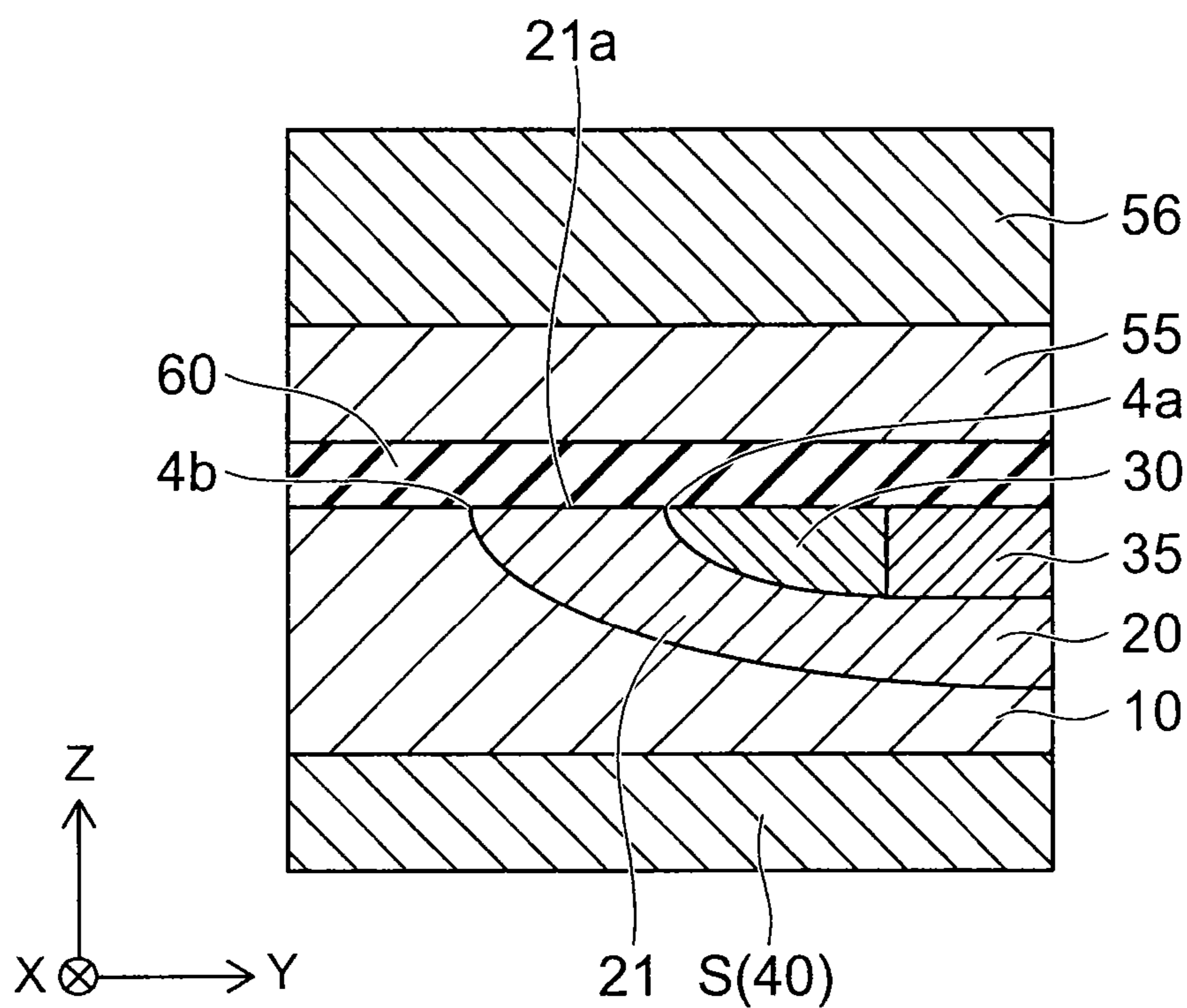


FIG. 9A

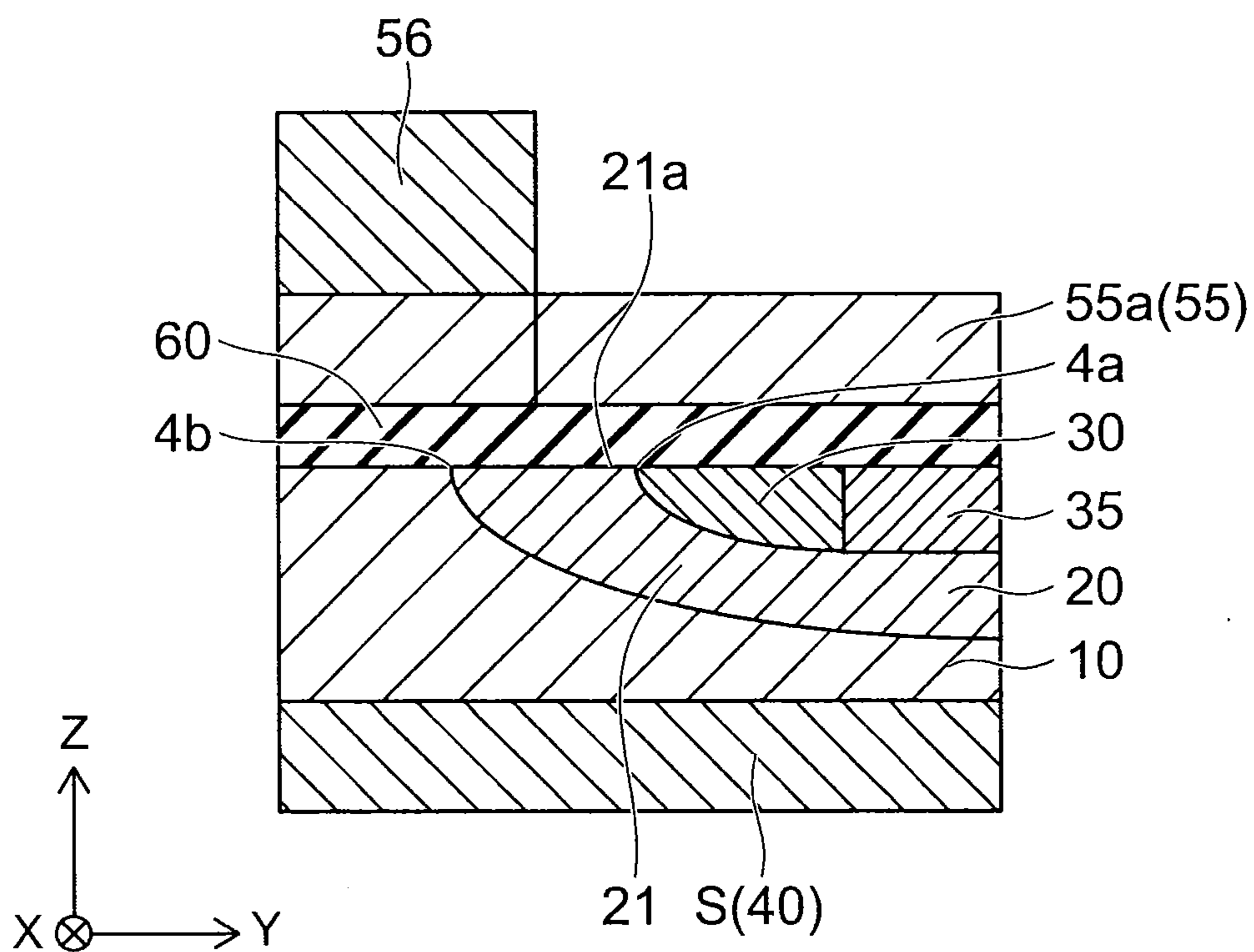


FIG. 9B

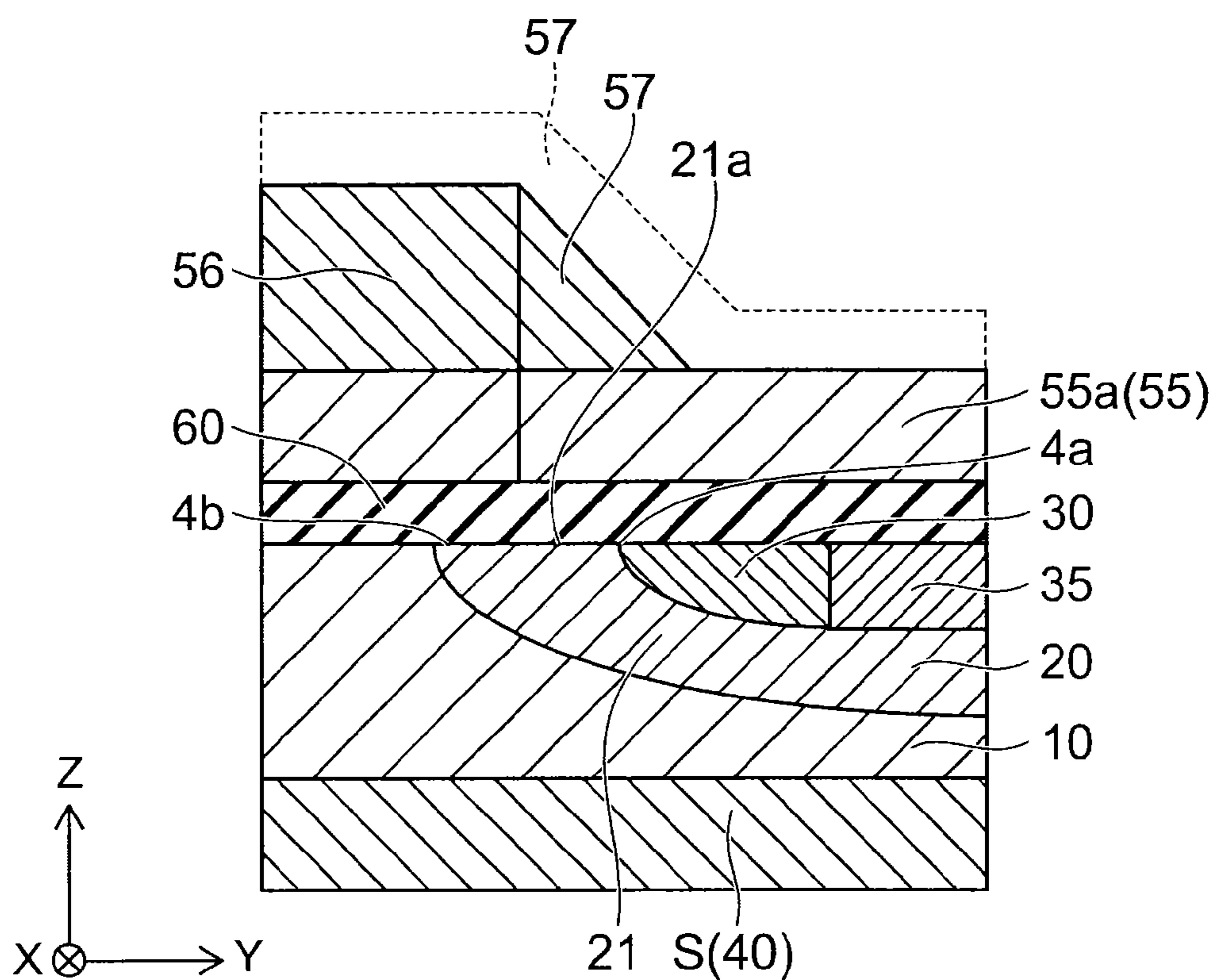


FIG. 10A

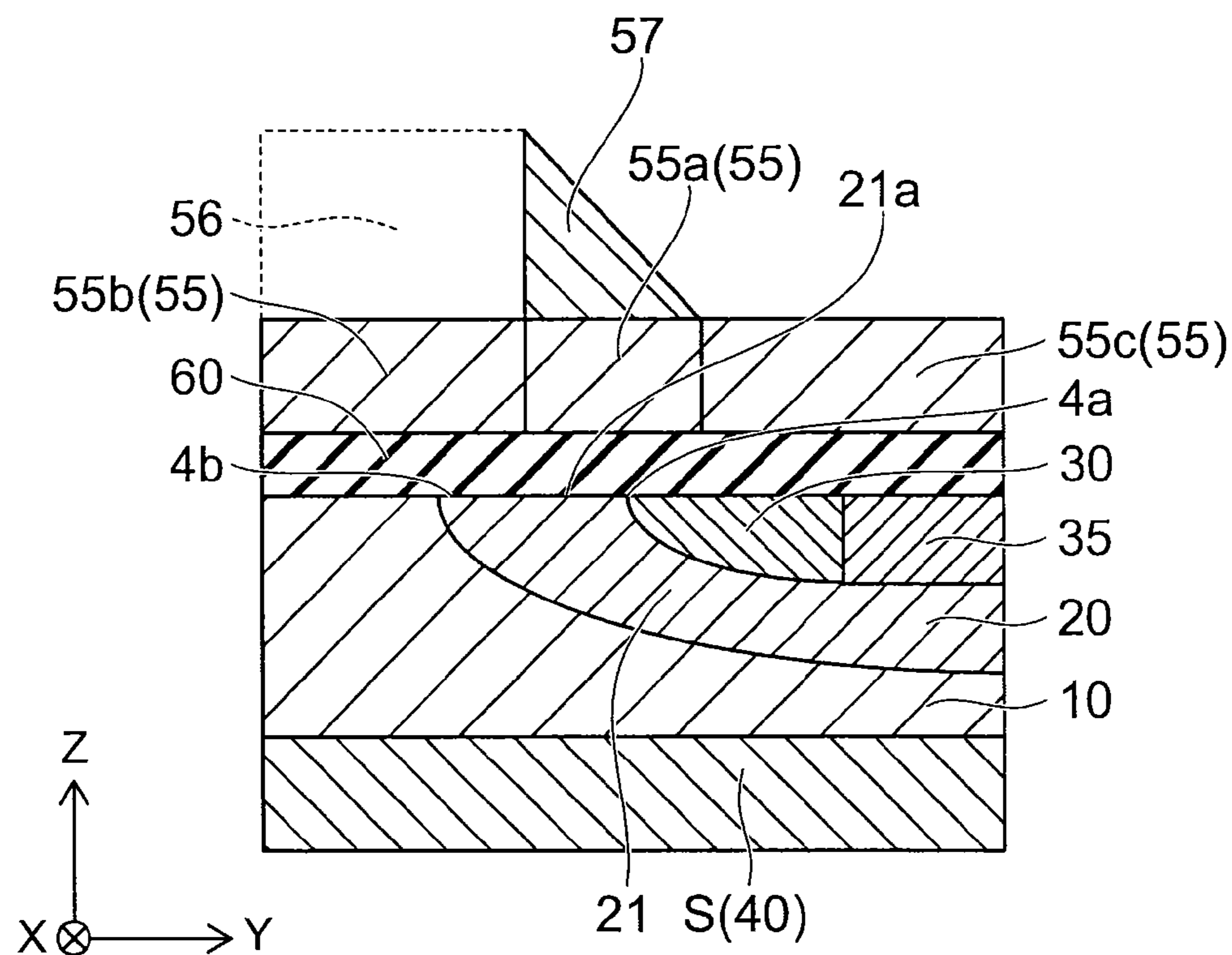


FIG. 10B

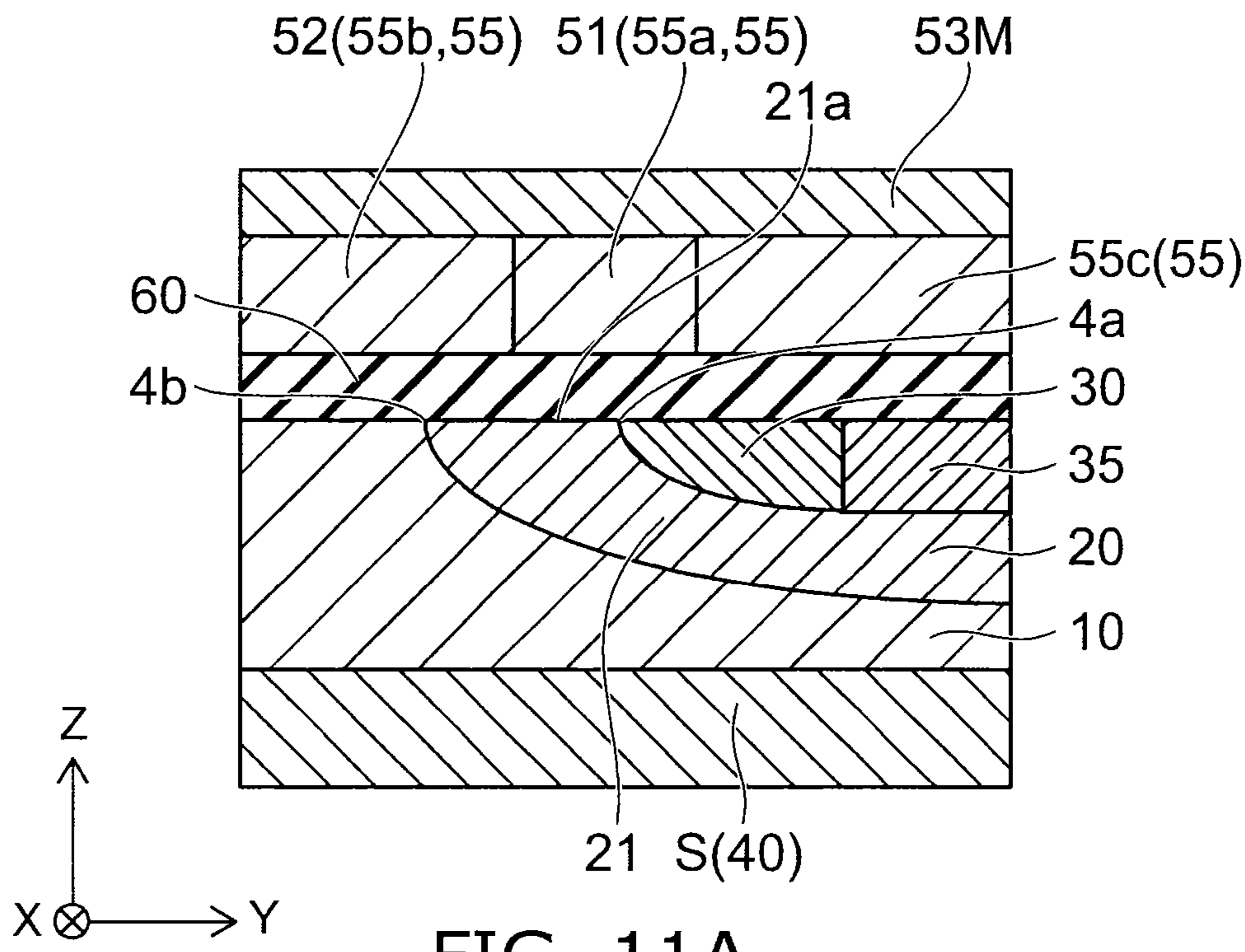


FIG. 11A

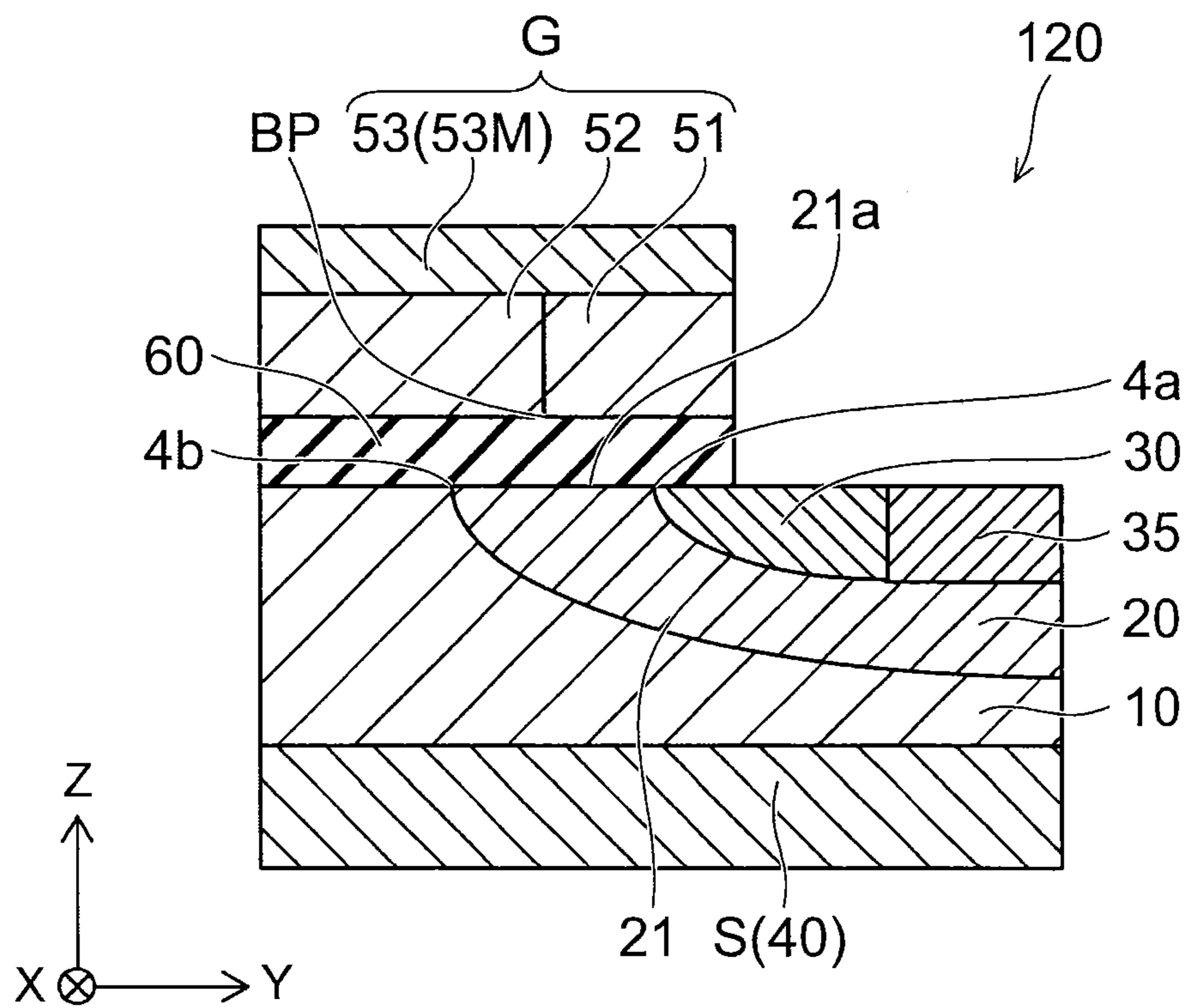


FIG. 11B

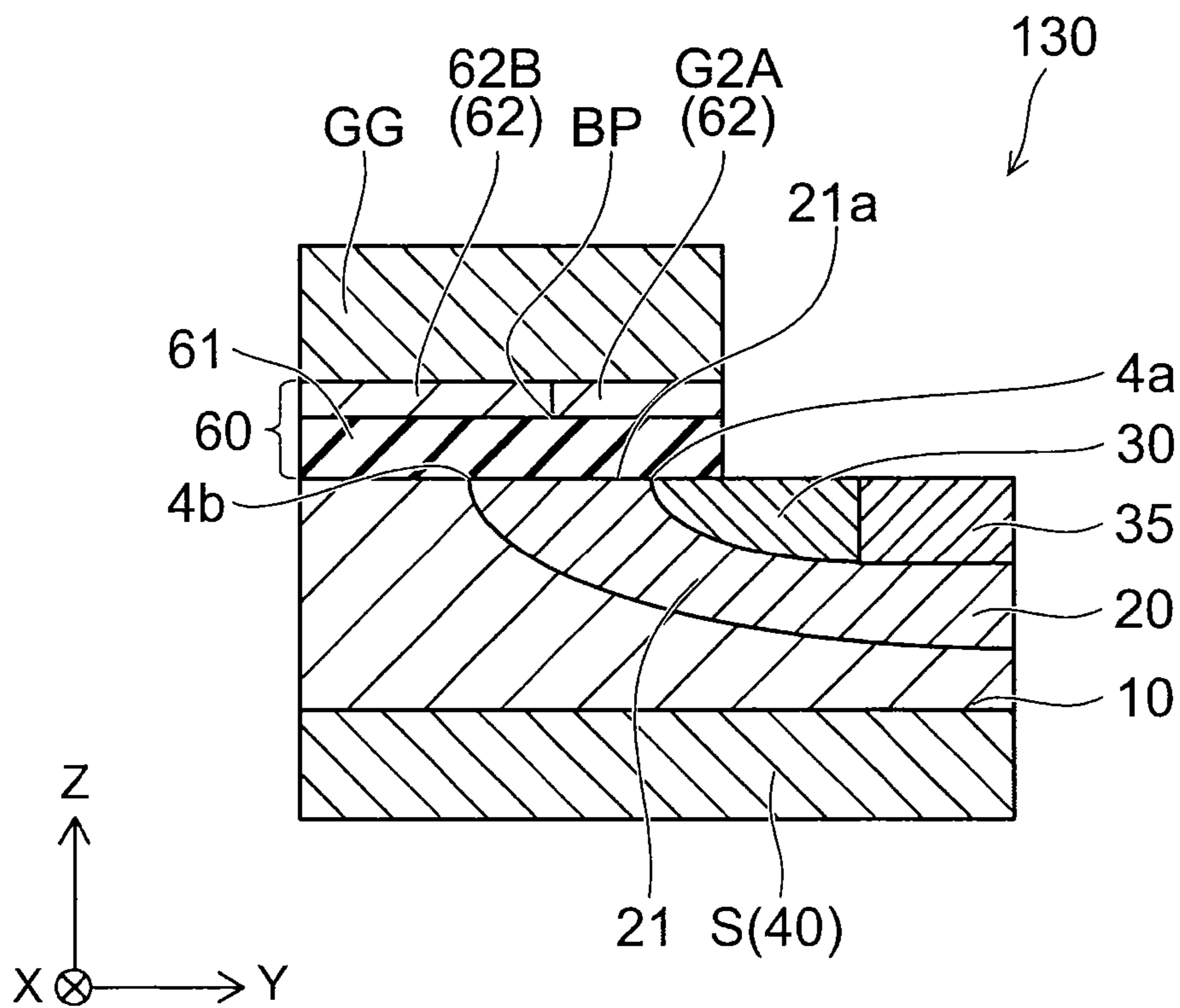


FIG. 12

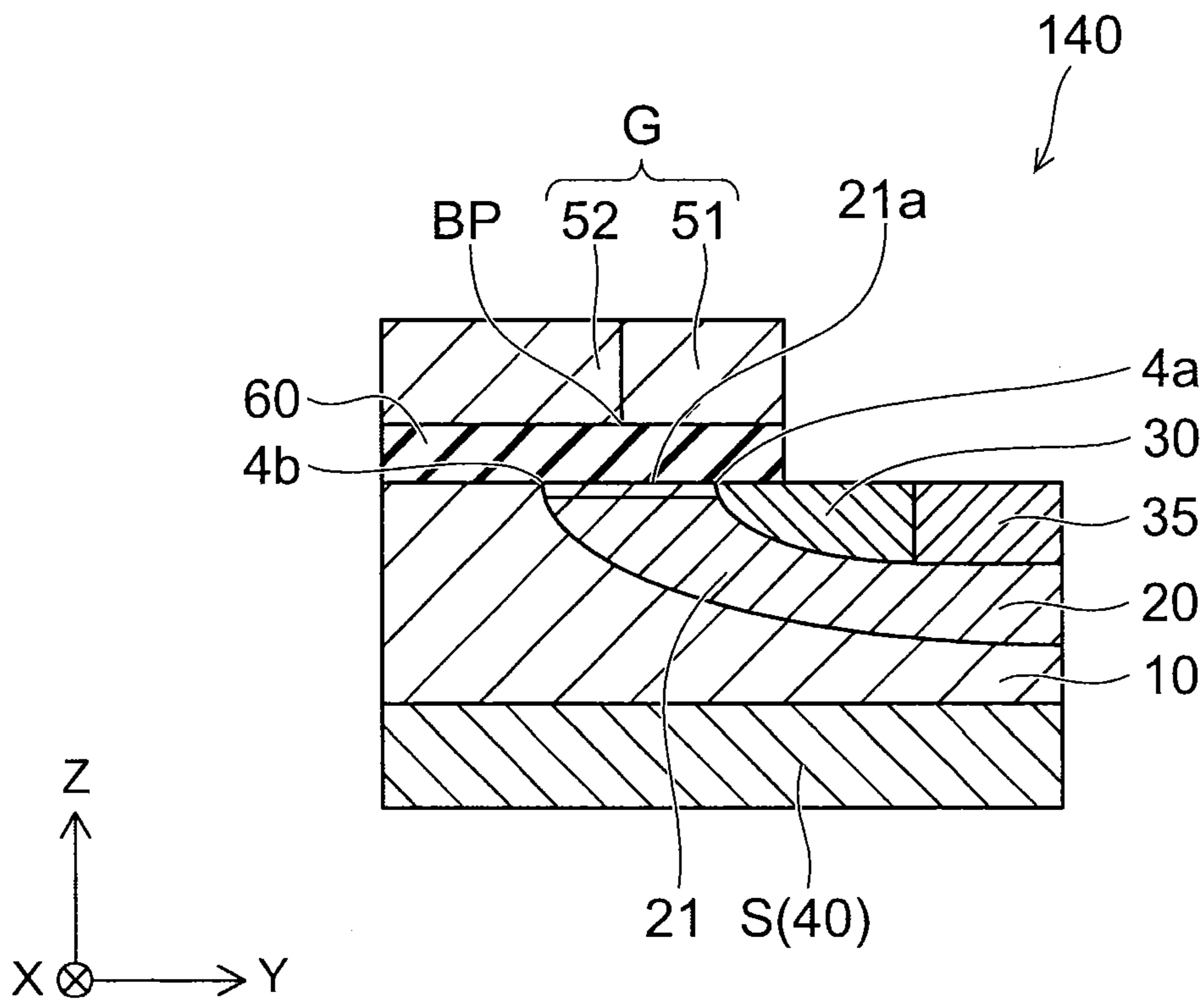


FIG. 13

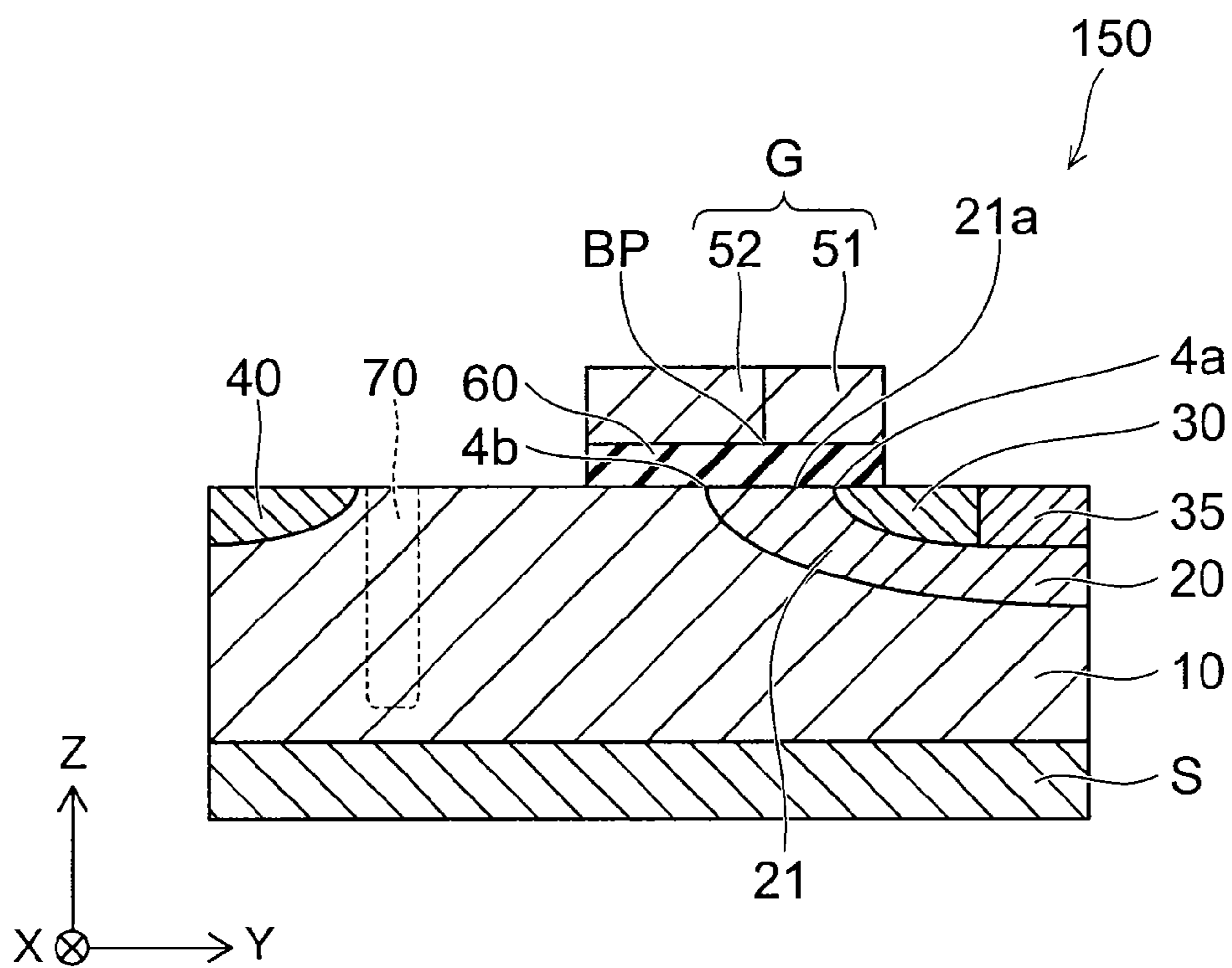


FIG. 14

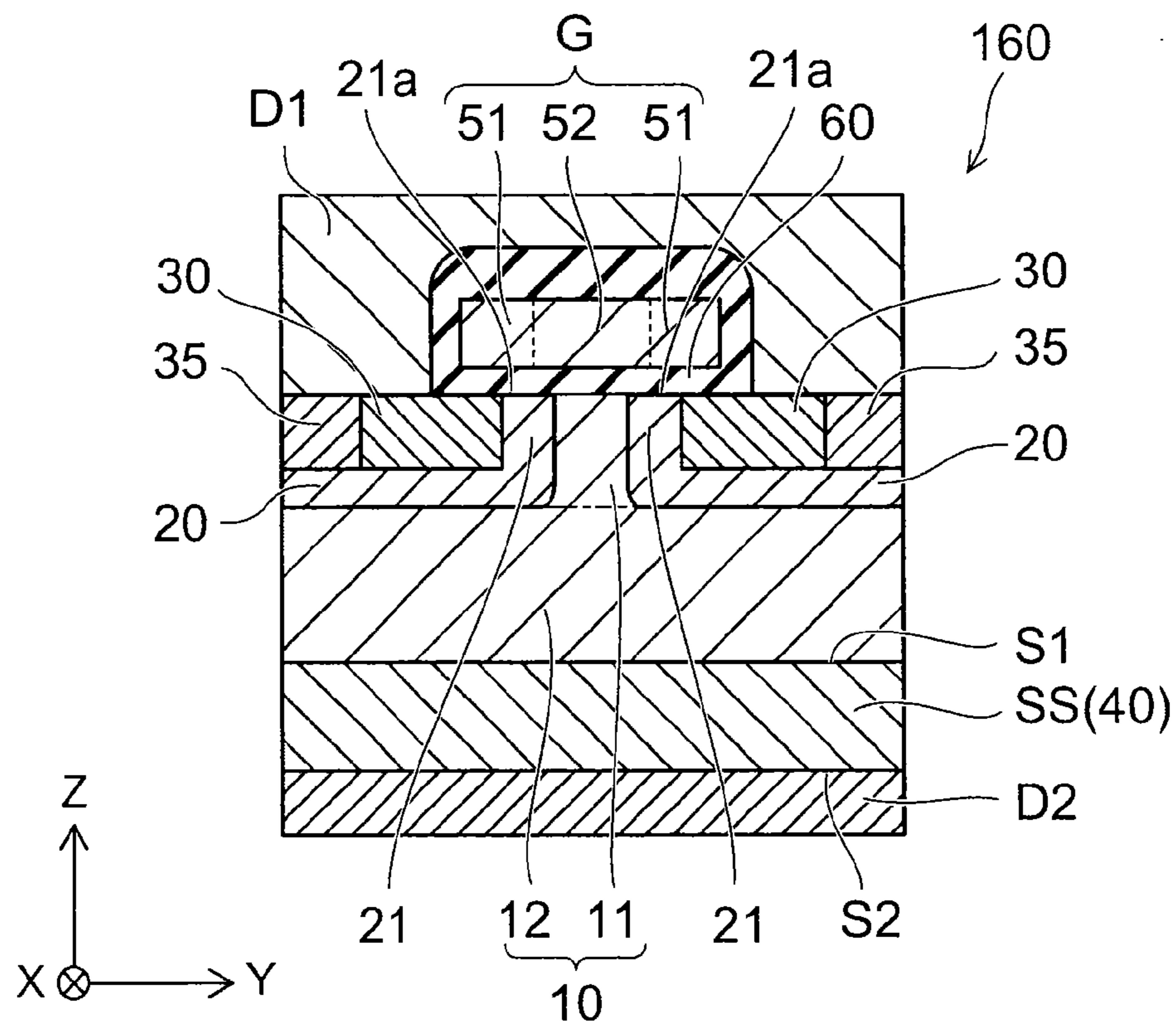


FIG. 15

SEMICONDUCTOR DEVICE

CROSS-REFERENCE TO RELATED APPLICATIONS

[0001] This application is based upon and claims the benefit of priority from the prior Japanese Patent Application [0002] No. 2012-070399, filed on Mar. 26, 2012; the entire contents of which are incorporated herein by reference.

FIELD

[0003] Embodiments described herein relate generally to a semiconductor device.

BACKGROUND

[0004] A silicon carbide (SiC) has an excellent physical property such that a band gap is triple, a breakdown electric field intensity is about tenfold and a thermal conductivity is about triple, in comparison with a silicon (Si). It is possible to realize a semiconductor device which has a low loss and is excellent in a high temperature operation, by using a characteristic of the SiC mentioned above.

[0005] In the semiconductor device using the SiC, in order to improve an electron transfer degree of an inversion layer and improve a reliability of a gate insulating film, it has been known to use a silicon dioxide (SiO₂) added a nitrogen (N) as the gate insulating film.

[0006] In the semiconductor device using the SiC mentioned above, it is important to adjust a threshold value of a gate voltage without deteriorating a current and voltage property.

BRIEF DESCRIPTION OF THE DRAWINGS

[0007] FIGS. 1A and 1B are schematic cross sectional views illustrating a configuration of a semiconductor device according to a first embodiment;

[0008] FIG. 2 is a schematic cross sectional view illustrating the boundary position;

[0009] FIG. 3 is a view showing a drain electric property of the semiconductor device;

[0010] FIG. 4 is a view showing a gate voltage dependency of the drain current;

[0011] FIGS. 5A and 5B are schematic cross sectional views showing the other configuration example of the semiconductor device according to the first embodiment;

[0012] FIG. 6A to FIG. 7B are schematic cross sectional views which exemplify the method of manufacturing the semiconductor device;

[0013] FIG. 8 is a schematic cross sectional view illustrating a configuration of a semiconductor device according to a second embodiment;

[0014] FIG. 9A to FIG. 11B are schematic cross sectional views which exemplify the method of manufacturing the semiconductor device;

[0015] FIG. 12 is a schematic cross sectional view illustrating a configuration of a semiconductor device according to a third embodiment;

[0016] FIG. 13 is a schematic cross sectional view illustrating a configuration of a semiconductor device according to a fourth embodiment;

[0017] FIG. 14 is a schematic cross sectional view illustrating a configuration of a semiconductor device according to a fifth embodiment; and

[0018] FIG. 15 is a schematic cross sectional view illustrating a configuration of a semiconductor device according to a sixth embodiment.

DETAILED DESCRIPTION

[0019] In general, according to one embodiment, a semiconductor device includes a first semiconductor region, a second semiconductor region, a third semiconductor region, an insulating film, and a control electrode. The first semiconductor region includes a silicon carbide of a first conductivity type. The second semiconductor region is provided on the first semiconductor region. The second semiconductor region includes a silicon carbide of a second conductivity type. The second semiconductor region has a first main surface. The third semiconductor region is provided on the second semiconductor region. The third semiconductor region includes the silicon carbide of the first conductivity type. The insulating film is provided at least on the first main surface of the second semiconductor region. The control electrode is provided on the insulating film. The control electrode has a first region close to the third semiconductor region side, and a second region closer to the first semiconductor region side than the first region. An effective work function of the first region is larger than an effective work function of the second region.

[0020] Various embodiments will be described hereinafter with reference to accompanying drawings.

[0021] The drawings are schematic and conceptual, and a relationship between a thickness and a width in each of the portions, and a rate of a magnitude between the portions are not necessarily identical to actual ones. Further, even in the case of showing the same portion, there is a case that the mutual dimensions and the rate are differently shown according to the drawings.

[0022] Further, in the specification and each of the drawings of the present application, the same reference numerals are attached to the same element as mentioned above with regard to the previously provided drawings, and a detailed description thereof will be appropriately omitted.

[0023] Further, in the following description, a specific example in which a first conductivity type is an n-type and a second conductivity type is a p-type is listed up as one example.

[0024] In the following description, reference symbols n⁺, n, n⁻, p⁺, p and p⁻ denote relative heights of an impurity concentration in each of the conductivity types. In other words, n⁺ indicates that the n-type impurity concentration is relatively higher than n, and n⁻ indicates that the n-type impurity concentration is relatively lower than n. Further, p⁺ indicates that the p-type impurity concentration is relatively higher than p, and p⁻ indicates that the p-type impurity concentration is relatively lower than p.

First Embodiment

[0025] FIGS. 1A and 1B are schematic cross sectional views illustrating a configuration of a semiconductor device according to a first embodiment.

[0026] FIG. 1A shows a schematic cross sectional view of a semiconductor device 110 according to the first embodiment, and FIG. 1B shows a schematic enlarged cross sectional view of a portion A in FIG. 1A.

[0027] As shown in FIGS. 1A and 1B, the semiconductor device 110 according to the embodiment is provided with a

first semiconductor region **10**, a second semiconductor region **20**, a third semiconductor region **30**, an insulating film **60**, and a control electrode **G**.

[0028] The semiconductor device **110** is a metal oxide semiconductor field effect transistor (MOSFET) including the silicon carbide (SiC).

[0029] The first semiconductor region **10** includes the SiC of a first conductivity type (n^- -type). The first semiconductor region **10** is formed on an upper face **S1** of a substrate **S** which includes the SiC of the first conductivity type (n^+ -type) shown in FIG. 1A, for example, by an epitaxial growth.

[0030] In this case, in the embodiment, a direction which is orthogonal to the upper face **S1** of the substrate **S** is referred to as a **Z** direction, one of directions which are orthogonal to the **Z** direction is referred to as an **X** direction, and a direction which is orthogonal to the **Z** direction and the **X** direction is referred to as a **Y** direction. Further, a direction which heads for the first semiconductor region **10** from the substrate **S** is referred to as an upper (an upper side), and a direction which heads for the substrate **S** from the first semiconductor region **10** is referred to as a lower (a lower side).

[0031] The first semiconductor region **10** has a first portion **11** and a second portion **12**. The first portion **11** is provided on a part of the second portion **12**. The first portion **11** is a junction field effect transistor (JFET) region of the MOSFET. The second portion **12** is a drift region of the MOSFET.

[0032] The second semiconductor region **20** is provided on the first semiconductor region **10**. The second semiconductor region **20** has a channel portion **21**. An upper face of the channel portion **21** is a first main surface **21a**. The channel portion **21** is provided adjacent to the first portion **11**. The second semiconductor region **20** includes the SiC of a second conductivity type (p -type). In other words, the second semiconductor region **20** is provided in the other portion than the part in which the first portion **11** is provided on the second portion **12**. The second semiconductor region **20** is a p -type well of the MOSFET.

[0033] A third semiconductor region **30** is provided on the second semiconductor region **20**. The third semiconductor region **30** is provided in a surface layer portion of the second semiconductor region **20** and includes the SiC of the first conductivity type (n^+ -type). The third semiconductor region **30** is a source region of the MOSFET.

[0034] The insulating film **60** is provided at least on the first main surface **21a** of the second semiconductor region **20**. The insulating film **60** which is provided between the first main surface **21a** and a control electrode **G** mentioned later is a gate insulating film of the MOSFET. Further, the insulating film **60** serves as a film which insulates between the control electrode **G** and a first electrode **D1** mentioned later. For example, a silicon oxide added a nitrogen is used as the insulating film **60**.

[0035] The control electrode **G** is provided on the insulating film **60**. In other words, the control electrode **G** is provided via the insulating film **60** which is provided on the first main surface **21a**. As a result, the control electrode **G** serves as a gate electrode of the MOSFET.

[0036] The control electrode **G** has a first region **51** close to the third semiconductor region side, and a second region **52** closer to the first semiconductor region **10** side than the first region **51**. As in the example shown in FIG. 1A, in the case that a pair of second semiconductor regions **20** and a pair of third semiconductor regions **30** are provided with respect to one control electrode **G**, the first region **51** is provided in both

end sides in the **Y** direction of one control electrode **G**, and the second region **52** is provided in a center portion.

[0037] In the semiconductor device **110**, an effective work function of the first region **51** is larger than an effective work function of the second region **52**.

[0038] In the semiconductor device **110** according to the embodiment, a threshold value of a gate voltage is adjusted by the control electrode **G**, without deteriorating the current and voltage property.

[0039] In the semiconductor device **110**, a fourth semiconductor region **40** is provided in the substrate **S**. The fourth semiconductor region **40** includes the SiC of the first conductivity type (n^+ -type). The fourth semiconductor region **40** is provided in the direction (the **Z** direction) which is orthogonal to the first main surface **21a** so as to be spaced from the second semiconductor region **20**. The fourth semiconductor region **40** is a drain region of the MOSFET. By providing the fourth semiconductor region **40** mentioned above, the semiconductor device **110** is configured to be a vertical type MOSFET.

[0040] A fifth semiconductor region **35** is provided in the semiconductor device **110**. The fifth semiconductor region **35** is provided in an opposite side to the channel portion **21** of the third semiconductor region **30** on the second semiconductor region **20**. The fifth semiconductor region **35** includes the SiC of the second conductivity type (p^+ -type). The fifth semiconductor region **35** is used as a contact region with the first electrode **D1** mentioned later.

[0041] The first electrode **D1** is provided in the semiconductor device **110**. The first electrode **D1** is electrically connected with the third semiconductor region **30**. The first electrode **D1** is electrically insulated from the control electrode **G** by the insulating film **60**. The first electrode **D1** comes into contact with the third semiconductor region **30**. The first electrode **D1** is a source electrode of the MOSFET.

[0042] In the embodiment, the first electrode **D1** also comes into contact with a fifth semiconductor region **50**. As a result, the first electrode **D1** serves as a common electrode of the source region of the MOSFET and the p -type well.

[0043] A second electrode **D2** is provided in the semiconductor device **110**. The second electrode **D2** is electrically connected with the fourth semiconductor region **40**. The second electrode **D2** is provided in a lower face **S2** in an opposite side to the upper face **S1** of the substrate **S**. The second electrode **D2** is a drain electrode of the MOSFET.

[0044] Next, a description will be given of a specific example of the semiconductor device **110** according to the first embodiment.

[0045] As shown in FIG. 1B, an n -type impurity having a high concentration is introduced into the fourth semiconductor region **40** (the drain region) which is provided in the substrate **S**. The second portion **12** (the drift layer) of the first semiconductor region **10** added the n -type impurity having a low concentration is introduced is connected to the fourth semiconductor region **40**.

[0046] The second semiconductor region **20** (the p -type well) added the p -type impurity is introduced is provided on a surface of the first semiconductor region **10**, and the third semiconductor region **30** (the source region) added the n -type impurity having a high concentration is introduced is provided on a surface of the second semiconductor region **20**. The fifth semiconductor region **35** (the contact region) added the p -type impurity having a high concentration is introduced

is provided in the surface of the second semiconductor region **20** in such a manner as to come into contact with the third semiconductor region **30**.

[0047] The insulating film **60** (the gate insulating film) is provided on the first portion **11** of the first semiconductor region **10**, the channel portion **21** of the second semiconductor region **20** and the third semiconductor region **30**.

[0048] The first region **51** and the second region **52** serving as the control electrode G (the gate electrode) are provided on the insulating film **60**.

[0049] The thicknesses of the first region **51** and the second region **52** are, for example, not less than 10 nanometer (nm) and not more than 10 millimeter (mm).

[0050] The effective work function of the first region **51** is larger than the effective work function of the second region **52**.

[0051] For example, a platinum (Pt) is used for a material of the first region **51**. For example, at least any of an aluminum (Al) and a titanium nitride (TiN) is used for a material of the second region **52**. A composition of the element included in the first region **51** is different from a composition of the element included in the second region **52**.

[0052] The first region **51** may be provided over a whole region in the direction (the X direction) in which the control electrode G extends, or may be provided in a part in the X direction.

[0053] In the control electrode G, the other region having an effective work function than the first region **51** and the second region **52** may be provided. In this case, a direction which connects the first semiconductor region **10** and the third semiconductor region **30** along the first main surface **21a** is set to the first direction (the Y direction), a region which is closest to the third semiconductor region **30** in the Y direction is set to the first region **51**, and a region which is adjacent to the first region **51** in the Y direction is set to the second region **52**.

[0054] In the semiconductor device **110**, a boundary position BP between the first region **51** and the second region **52** is provided at a position which overlaps the first main surface **21a** as view in the direction (the Z direction) which is orthogonal to the first main surface **21a**. In other words, the boundary position BP in an interface between the control electrode G and the insulating film **60** exists above a region which is sandwiched by a boundary (hereinafter, refer to as a source end **4a**) between the second semiconductor region **20** and the third semiconductor region **30** in the first main surface **21a**, and a boundary (hereinafter, refer to as a drain end **4b**) between the second semiconductor region **20** and the first semiconductor region **10**. Further, it is desired that a distance in the Y direction from the drain end **4b** to the boundary position BP becomes shorter than a distance in the Y direction from the source end **4a** to the boundary position BP.

[0055] In this case, a description will be given of a favorable example of the boundary position.

[0056] FIG. 2 is a schematic cross sectional view illustrating the boundary position.

[0057] FIG. 3 is a view showing a drain electric property of the semiconductor device.

[0058] FIG. 4 is a view showing a gate voltage dependency of the drain current.

[0059] FIG. 2 shows a definition of the boundary position BP between the first region **51** and the second region **52** of the control electrode G. As shown in FIG. 2, a distance (a channel length) in the Y direction between the source end **4a** and the drain end **4b** is set to L, and a distance in the Y direction from

the drain end **4b** to the boundary position BP is set to X_{ov} . The property of the semiconductor device **110** is adjusted by the X_{ov} .

[0060] FIG. 3 shows a comparison of the drain current property (a horizontal axis is a gate voltage, and a vertical axis is a drain current) of the vertical type MOSFET. In this case, the drain current property of the various vertical type MOSFET is simulated by assuming the distance L to 1 micrometer (μm).

[0061] FIG. 3 shows results of simulation of the drain current property of the semiconductor devices **110** and **111** according to the embodiment, and semiconductor devices **191** and **192** according to reference examples.

[0062] In the semiconductor device **110** according to the embodiment, $X_{ov}=0.35 \mu\text{m}$ is established. In the semiconductor device **111**, $X_{ov}=0.0 \mu\text{m}$ is established. In the semiconductor device **191** according to the first reference example, all the control electrodes G are formed of the same material as the first region **51** (equivalent to $X_{ov}<0$). In semiconductor device **192** according to the second reference example, all the control electrodes G are formed of the same material as the second region **52**, and the p-type impurity is additionally implanted into the channel portion **21** (equivalent to $X_{ov}>L$).

[0063] As shown in FIG. 3, in the semiconductor devices **110** and **111** according to the embodiment, a clear increase of the drain current is confirmed in comparison with the semiconductor devices **191** and **192** according to the reference examples. In the semiconductor device **111**, the drain current is increased, however, the threshold value of the gate voltage is lower than that of the other semiconductor devices **110**, **191** and **192**.

[0064] On the basis of the result of simulation, $0 \leq X_{ov} \leq L$ is desired. In other words, it is desired that the boundary position BP is provided at a position which overlaps the first main surface **21a** as view in the Z direction. Furthermore, $0 < X_{ov}$ is further desired. In this case, an error in manufacturing is included in $X_{ov}=0$ and $X_{ov}=L$. Further, in the semiconductor device **110** according to the embodiment, X_{ov} may be slightly less than 0 or may be slightly more than L, according to a specification.

[0065] FIG. 4 shows a result obtained by simulation calculating a gate voltage dependency of the drain current. In the simulation calculation, X_{ov} is changed step by step from 0.0 μm to 0.50 μm . For comparison, an electric property ("Ideal SiC-MOSFET" curve) of a virtual SiC vertical MOSFET having an ideal MOS interface is shown.

[0066] A threshold voltage in the case that X_{ov} is not less than 0.25 μm and not more than 0.5 μm is the same level as a threshold voltage of the virtual vertical type MOSFET. In the case of $X_{ov}=0.50 \mu\text{m}$, it is understood that the threshold value becomes lower in comparison with the virtual vertical MOSFET. This is because a potential controllability of the surface of the channel portion **21** by the control electrode G (the gate electrode) in the vicinity of the source region is lowered, since the boundary position BP comes close to the third semiconductor region **30** (the source region) according to the increase of X_{ov} .

[0067] Considering the calculation on the assumption of $L=1 \mu\text{m}$ which is a typical channel length, these results show that X_{ov}/L is desired to be not less than 0 and less than 0.5. by setting the X_{ov} as mentioned above, in the semiconductor

device **110** accordance with the embodiment, the threshold value of the gate voltage is adjusted without deteriorating the current and voltage property.

[0068] FIGS. **5A** and **5B** are schematic cross sectional views showing the other configuration example of the semiconductor device according to the first embodiment.

[0069] FIGS. **5A** and **5B** show an enlarged schematic cross sectional views of the periphery of the control electrode **G**.

[0070] In a semiconductor device **112** shown in FIG. **5A**, the first region **51** and the second region **52** are provided in an boundary face side of the control electrode **G** with the insulating film **60**. The control electrode **G** includes a third region **53** which is provided in an opposite side to the insulating film **60** of the first region **51** and the second region **52**. An electric resistance value of the third region **53** is smaller than an electric resistance value of the first region **51** and an electric resistance value of the second region **52**.

[0071] In a semiconductor device **113** shown in FIG. **5B**, it is configured such that the first region **51** of the control electrode **G** covers the above of the second region **52**. In other words, the first region **51** covers an upper face and a side face of the second region **52**. A portion **51a** which is provided in an outer side than the side face of the second region **52** in the first region **51** comes into contact with the insulating film **60** in a region which overlaps the first main surface **21a** as view in the **Z** direction. The third region **53** may be provided on the second region **52**.

[0072] In any of the semiconductor devices **112** and **113** shown in FIGS. **5A** and **5B**, the same operation and effect as the semiconductor device **110** can be obtained by setting **Xov** of the boundary position **BP** between the first region **51** and the second region **52** as mentioned above.

[0073] Next, a description will be given of a method of manufacturing the semiconductor device **113**.

[0074] FIG. **6A** to FIG. **7B** are schematic cross sectional views which exemplify the method of manufacturing the semiconductor device.

[0075] First of all, as shown in FIG. **6A**, the first semiconductor region **10**, the second semiconductor region **20**, the third semiconductor region **30**, the fourth semiconductor region and the fifth semiconductor region **50** are formed by introducing each of the impurities to the substrate **S** of **SiC**. The first semiconductor region **10** and the second semiconductor region **20** may be formed by implanting the impurity to the substrate **S** or may be formed by an epitaxial growth on the substrate **S**.

[0076] Next, the insulating film **60** is formed on the first semiconductor region **10**, the second semiconductor region **20**, the third semiconductor region **30** and the fifth semiconductor region **50**. For example, a silicon oxide added a nitrogen is used in the insulating film **60**.

[0077] Next, a second region material **52M** is deposited on the insulating film **60**. A thickness of the second region material **52M** is, for example, not less than 0.1 nm and not more than 10 nm. The second region material **52M** is, for example, at least one which is selected from **Al** and **TiN**.

[0078] Next, a lithography process and an etching process are applied to the second region material **52M**. As a result, the second region **52** is formed as shown in FIG. **6B**.

[0079] Next, as shown in FIG. **7A**, a first region material **51M** is deposited on the second region **52**, and a third region material **53M** is deposited on the first region material **51M**. A thickness of the first region material **51M** is, for example, not less than 0.1 nm and not more than 10 nm. The first region

material **51M** is, for example, **Pt**. A thickness of the third region material **53M** is, for example, not less than 10 nm and not more than 10 nm. The third region material **53M** is, for example, at least one which is selected from the n-type or p-type silicon, **TiN**, **W**, **Al**, **TaN** and **NiSi**.

[0080] Next, the lithography process and the etching process are applied to the first region material **51M** and the third region material **53M**. As a result, as shown in FIG. **7B**, the control electrode **G** having the first region **51** which covers the second region **52** and the third region **53** which is provided on the first region **51** is formed. As a result, the semiconductor device **113** is completed.

Second Embodiment

[0081] FIG. **8** is a schematic cross sectional view illustrating a configuration of a semiconductor device according to a second embodiment.

[0082] As shown in FIG. **8**, in a semiconductor device **120** according to the second embodiment, the material of the control electrode **G** is different from the semiconductor device **110** according to the first embodiment.

[0083] In the semiconductor device **120**, the first region **51** and the second region **52** include a polysilicon (polycrystalline silicon) added the impurity is implanted. For example, a p-type polysilicon is used in the first region **51**, and an n-type polysilicon is used in the second region **52**.

[0084] The control electrode **G** includes the third region **53** which is provided on the first region **51** and the second region **52**. A material having a lower electric resistance value than the first region **51** and the second region **52** is used in the third region **53**. For example, at least one which is selected from **TiN**, **W**, **Al**, **TaN**, **Ni**, **Cu**, **NiSi** and **NiPtSi** is used in the third region **53**.

[0085] In the semiconductor device **120** according to the second embodiment, a threshold value of the gate voltage can be adjusted without deteriorating the current and voltage property by setting the boundary position **BP** between the first region **51** and the second region **52** in the same manner as the semiconductor device **110** according to the first embodiment. Further, since the polysilicon is used as the first region **51** and the second region **52**, it is easy to process in comparison with the case of using a metal.

[0086] Next, a description will be given of a method of manufacturing the semiconductor device **120**.

[0087] FIG. **9A** to FIG. **11B** are schematic cross sectional views which exemplify the method of manufacturing the semiconductor device.

[0088] First of all, as shown in FIG. **9A**, the first semiconductor region **10**, the second semiconductor region **20**, the third semiconductor region **30**, the fourth semiconductor region and the fifth semiconductor region **50** are formed by introducing each of the impurities to the substrate **S** of **SiC**. The first semiconductor region **10** and the second semiconductor region **20** may be formed by implanting the impurity to the substrate **S** or may be formed by an epitaxial growth on the substrate **S**.

[0089] Next, the insulating film **60** is formed on the first semiconductor region **10**, the second semiconductor region **20**, the third semiconductor region **30** and the fifth semiconductor region **50**. For example, a silicon oxide added a nitrogen is used in the insulating film **60**.

[0090] Next, a neutral polysilicon film **55** is deposited on the insulating film **60**. A silicon oxide film **56** is deposited on the polysilicon film **55**.

[0091] Next, as shown in FIG. 9B, a lithography process is applied to the silicon oxide film 56, and an anisotropic etching is thereafter carried out. As a result, a surface of a part of the polysilicon film 55 is exposed.

[0092] Thereafter, an ion-implantation is carried out by using the silicon oxide film 56 as a mask, and a p-type impurity is introduced to an exposed portion 55a of the polysilicon film 55.

[0093] Next, as shown in FIG. 10A, a silicon nitride film 57 is left only on a side face of the silicon oxide film 56 by carrying out the anisotropic etching after depositing the silicon nitride film 57 on the silicon oxide film 56 and the first region 51.

[0094] Next, as shown in FIG. 10B, the polysilicon film 55 except the portion 55a in which the silicon nitride film 57 exists is exposed by peeling off the silicon oxide film 56. Thereafter, the n-type impurity is introduced according to an ion-implantation into the exposed polysilicon film 55. As a result, in the portion 55a of the polysilicon film 55 below the silicon nitride film 57, a state in which the p-type impurity is introduced is maintained. Further, the n-type impurity is introduced into the portions 55b and 55c of the polysilicon film 55 in which the silicon nitride film 57 is not formed.

[0095] Next, an activation of the impurity which is introduced into the polysilicon film 55 is carried out by an annealing process, after peeling off the silicon nitride film 57. As a result, the portion 55a of the polysilicon film 55 becomes the first region 51, and the portion 55b of the polysilicon film 55 becomes the second region 52. Thereafter, as shown in FIG. 11A, the third region material 53M is deposited on the polysilicon film 55.

[0096] Next, as shown in FIG. 11B, by carrying out the lithography process and the etching process, the third region material 53M, a part of the polysilicon film 55 and a part of the insulating film 60 are removed. The control electrode G including the first region 51, the second region 52 and the third region 53 is formed. As a result, the semiconductor device 120 is completed.

Third Embodiment

[0097] FIG. 12 is a schematic cross sectional view illustrating a configuration of a semiconductor device according to a third embodiment.

[0098] A schematic enlarged cross sectional view of the periphery of the control electrode G is shown in FIG. 12.

[0099] As shown in FIG. 12, a semiconductor device 130 according to the third embodiment is provided with the first semiconductor region 10, the second semiconductor region 20, the third semiconductor region 30, the insulating film 60 and a control electrode GG.

[0100] In the semiconductor device 130, the fourth semiconductor region 40 is provided in the substrate S. The fourth semiconductor region 40 includes the SiC of the first conductivity type (n⁺-type). The fourth semiconductor region 40 is provided in the direction (the Z direction) which is orthogonal to the first main surface 21a so as to be spaced from the second semiconductor region 20. The fourth semiconductor region 40 is the drain region of the MOSFET. The semiconductor device 130 mentioned above is the vertical type MOSFET including the SiC.

[0101] The fifth semiconductor region 35 is provided in the semiconductor device 130. The fifth semiconductor region 35 is provided in an opposite side to the channel portion 21 of the third semiconductor region 30 on the second semiconductor

region 20. The fifth semiconductor region 35 includes the SiC of the second conductivity type (p⁺-type).

[0102] In the semiconductor device 130, the insulating film 60 includes a first layer 61 and a metal oxide layer 62. The first layer 61 is provided on the first main surface 21a of the second semiconductor region 20, and the metal oxide layer 62 is provided on the first layer 61.

[0103] The metal oxide layer 62 has a first region 62A close to the third semiconductor region 30 side, and a second region 62B closer to the first semiconductor region 10 side than the first region 62A. An effective work function of the first region 62A is larger than an effective work function of the second region 62B.

[0104] In the semiconductor device 130 according to the embodiment, the threshold value of the gate voltage is adjusted without deteriorating the current and voltage property in the same manner as the semiconductor device 110 according to the first embodiment, by the insulating film 60.

[0105] Next, a description will be given of a specific example of the semiconductor device 130 according to the third embodiment.

[0106] As shown in FIG. 12, the fourth semiconductor region 40, the first semiconductor region 10, the second semiconductor region 20, the third semiconductor region and the fifth semiconductor region 50 on the substrate S are the same as the first embodiment.

[0107] The insulating film 60 is provided at least on the first surface 21a of the second semiconductor region 20. For example, the silicon oxide added the nitrogen is used in the first layer 61 of the insulating film 60. In the metal oxide layer 62 which is provided on the first layer 61, a metal element included in the first region 62A is at least one of Al and Mg. In the metal oxide layer 62, the metal element included in the second region 62B is, for example, at least one of La, Dy, Sr and Ba. It is configured such that an effective work function of the first region 62A becomes larger than an effective work function of the second region 62B, by selecting a material of each of the first region 62A and the second region 62B.

[0108] A material of the control electrode GG is, for example, at least one which is selected from the n-type or p-type silicon, TiN, W, Al, TaN and NiSi.

[0109] Thicknesses of the first region 62A and the second region 62B of the metal oxide layer 62 are thinner than a thickness of the control electrode GG, for example, not less than 0.1 nm and not more than 1 nm.

[0110] The first region 62A and the second region 62B of the metal oxide layer 62 are formed by carrying out the lithography process and the etching process after depositing the metal oxide on the first layer 61 of the insulating film 60. Further, the first region 62A and the second region 62B of the metal oxide layer 62 may be formed by forming the first layer 61 of the insulating film 60, depositing the metal mentioned above included in the first region 62A and the second region 62B thereon, and thereafter oxidizing the metal by heating at a higher temperature than a room temperature.

[0111] A boundary position BP' between the first region 62A and the second region 62B is provided at a position which overlaps the first main surface 21a as view in the direction (the Z direction) which is orthogonal to the first main surface 21a. Further, it is desired that a distance in the Y direction from the drain end 4b to the boundary position BP' becomes shorter than a distance in the Y direction from the source end 4a to the boundary position BP'.

[0112] In the semiconductor device **130** mentioned above, the threshold value of the gate voltage is adjusted without deteriorating the current and voltage characteristic by configuring the insulating film **60** having the boundary position BP' as mentioned above.

Fourth Embodiment

[0113] FIG. **13** is a schematic cross sectional view illustrating a configuration of a semiconductor device according to a fourth embodiment.

[0114] As shown in FIG. **13**, in a semiconductor device **140** according to the fourth embodiment, a region **22** into which the n-type impurity is introduced is provided in a surface layer of the channel portion **21** of the second semiconductor region **20**.

[0115] The semiconductor device **140** in which the region **22** mentioned above is provided in the surface layer of the channel portion **21** is a depletion type MOSFET.

[0116] In the semiconductor device **140** shown in FIG. **13**, the region **22** is provided in the surface layer of the channel portion **21** of the semiconductor device **110** according to the first embodiment shown in FIG. **1B**, however, the region **22** may be provided in the surface layer of the channel portion **21** of the semiconductor device **120** according to the second embodiment, and the semiconductor device **130** according to the third embodiment.

[0117] Even in the semiconductor device **140** which is the depletion type MOSFET mentioned above, the threshold value of the gate voltage can be adjusted without deteriorating the current and voltage property, in the same manner as the semiconductor device **110** according to the first embodiment.

Fifth Embodiment

[0118] FIG. **14** is a schematic cross sectional view illustrating a configuration of a semiconductor device according to a fifth embodiment.

[0119] As shown in FIG. **14**, in a semiconductor device **150** according to the fifth embodiment, the fourth semiconductor region **40** is provided in the direction (the Y direction) along the first main surface **21a** of the second semiconductor region **20** so as to be spaced from the second semiconductor region **20**. In other words, the semiconductor device **150** is a transverse type MOSFET including SiC.

[0120] In the semiconductor device **150**, an insulating region **70** may be provided between the second semiconductor region **20** and the fourth semiconductor region **40**, in the first semiconductor region **10**. The insulating region **70** is configured such that an insulating material is embedded within a trench which is formed at a predetermined depth from the surface of the first semiconductor region **10**. By providing the insulating region **70**, an effective distance between the second semiconductor region **20** and the fourth semiconductor region **40** becomes longer, and a breakdown voltage is improved.

[0121] Even in the semiconductor device **150** which is the transverse type MOSFET mentioned above, the threshold value of the gate voltage can be adjusted without deteriorating the current and voltage property, in the same manner as the semiconductor device **110** according to the first embodiment.

Sixth Embodiment

[0122] FIG. **15** is a schematic cross sectional view illustrating a configuration of a semiconductor device according to a sixth embodiment.

[0123] As shown in FIG. **15**, a semiconductor device **160** according to the sixth embodiment is an insulated gate bipolar transistor (IGBT).

[0124] In the semiconductor device **160**, a conductivity type of a substrate SS is different from the conductivity type of the substrate S of the semiconductor device **110** according to the first embodiment. In other words, while the conductivity type of the substrate S of the semiconductor device **110** is the n⁺-type, the conductivity type of the substrate SS of the semiconductor device **160** is the p⁺-type. The semiconductor device **160** is the same as the semiconductor device **110** except a point that the conductivity types of the substrates S and SS are different.

[0125] The substrate SS is a hexagonal SiC substrate which includes an impurity, for example, Al at an impurity concentration appropriately not less than $5 \times 10^{18} \text{ cm}^{-3}$ and not more than $1 \times 10^{19} \text{ cm}^{-3}$ as the p-type impurity. In the semiconductor device **160** corresponding to the IGBT, the control electrode G is a gate electrode, the first electrode D1 is an emitter electrode, and the second electrode D2 is a collector electrode.

[0126] Even in the semiconductor device **160** corresponding to the IGBT mentioned above, the threshold value of the gate voltage is adjusted without deteriorating the current and voltage property, in the same manner as the semiconductor device **110** according to the first embodiment.

[0127] As described above, according to the semiconductor device according to the embodiment, it is possible to adjust the threshold value of the gate voltage without deteriorating the current and voltage property.

[0128] The embodiments and the variations are described above, however, the invention is not limited to these examples. For example, even if those skilled in the art appropriately adds and deletes the configuration elements, and apply design changes to each of the embodiments and the variations, or appropriately combines the features of each of the embodiments, they are included in the scope of the invention as long as they are provided with the gist of the invention.

[0129] For example, in each of the embodiments and each of the variations mentioned above, the description is given by setting the first conductivity type to the n-type and the second conductivity type to the p-type, however, the invention can be executed if the first conductivity type is set to the p-type and the second conductivity type is set to the n-type.

[0130] While certain embodiments have been described, these embodiments have been presented by way of example only, and are not intended to limit the scope of the inventions. Indeed, the novel embodiments described herein may be embodied in a variety of other forms; furthermore, various omissions, substitutions and changes in the form of the embodiments described herein may be made without departing from the spirit of the inventions. The accompanying claims and their equivalents are intended to cover such forms or modifications to as would fall within the scope and spirit of the invention.

What is claimed is:

1. A semiconductor device comprising:
 - a first semiconductor region including a silicon carbide of a first conductivity type;

a second semiconductor region provided on the first semiconductor region, the second semiconductor region including a silicon carbide of a second conductivity type, the second semiconductor region having a first main surface;

a third semiconductor region provided on the second semiconductor region, the third semiconductor region including the silicon carbide of the first conductivity type;

an insulating film provided at least on the first main surface of the second semiconductor region; and

a control electrode provided on the insulating film, the control electrode having a first region close to the third semiconductor region side, and a second region closer to the first semiconductor region side than the first region, an effective work function of the first region being larger than an effective work function of the second region.

2. The device according to claim **1**, wherein the first region and the second region are provided in an boundary face side between the control electrode and the insulating film.

3. The device according to claim **2**, wherein the control electrode includes a third region provided in an opposite side to the insulating film in the first region and the second region.

4. The device according to claim **3**, wherein an electric resistance value of the third region is smaller than an electric resistance value of the first region and an electric resistance value of the second region.

5. The device according to claim **1**, wherein the first region and the second region include a polysilicon, the polysilicon added an impurity.

6. The device according to claim **5**, wherein the first region is a second conductivity type and the second region is a first conductivity type.

7. The device according to claim **1**, wherein the first region is adjacent to the second region in a first direction, the first direction connecting the first semiconductor region and the third semiconductor region, and being along the first main surface, and a boundary position between the first region and the second region is provided at a position overlapping the first main surface as view in a direction being orthogonal to the first main surface.

8. The device according to claim **7**, wherein in the case of setting a length in the first direction of the first main surface on the basis of an end portion in an opposite side to the third semiconductor region of the first main surface to L , and a distance in the first direction of the boundary position on the basis of the end portion to X , X/L is not less than 0 and less than 0.5 .

9. The device according to claim **1**, wherein the insulating film includes a silicon oxide added a nitrogen.

10. The device according to claim **1**, wherein a composition of an element included in the first region is different from a composition of an element included in the second region.

11. The device according to claim **1**, further comprising a fourth semiconductor region including the silicon carbide of the first conductivity type,

the fourth semiconductor region provided in a direction orthogonal to the first main surface so as to be spaced from the second semiconductor region.

12. The device according to claim **1**, further comprising a fourth semiconductor region including the silicon carbide of the first conductivity type,

the fourth semiconductor region provided in a direction along the first main surface so as to be spaced from the second semiconductor region.

13. The device according to claim **1**, further comprising: a fourth semiconductor region contacting with the first semiconductor region, the fourth semiconductor region including the silicon carbide of the first conductivity type;

a first electrode electrically connected with the third semiconductor region; and

a second electrode electrically connected with the fourth semiconductor region.

14. The device according to claim **1**, further comprising: a substrate provided between the first semiconductor region and the second electrode, the substrate including the silicon carbide.

15. The device according to claim **14**, wherein the substrate has a conductivity type of the first conductivity type.

16. The device according to claim **14**, wherein the substrate has a conductivity type of the second conductivity type.

17. A semiconductor device comprising:

a first semiconductor region including a silicon carbide of a first conductivity type;

a second semiconductor region provided on the first semiconductor region, the second semiconductor region including a silicon carbide of a second conductivity type and the second semiconductor region having a first main surface;

a third semiconductor region provided on the second semiconductor region, the third semiconductor region including the silicon carbide of the first conductivity type;

an insulating film provided at least on the first main surface of the second semiconductor region and includes a metal oxide layer; and

a control electrode provided on the insulating film, the metal oxide layer has a first region close to the third semiconductor region side, and a second region closer to the first semiconductor region side than the first region, and an effective work function of the first region being larger than an effective work function of the second region.

18. The device according to claim **17**, wherein the insulating film includes a first layer provided between the first main surface and the metal oxide layer, and the first layer includes a silicon oxide added a nitrogen.

19. The device according to claim **17**, wherein the first region is adjacent to the second region in a first direction, the first direction connecting the first semiconductor region and the third semiconductor region, and being along the first main surface, and a boundary position between the first region and the second region is provided at a position overlapping the first main surface as view in a direction orthogonal to the first main face.

20. The device according to claim **17**, wherein in the case of setting a length in the first direction of the first main surface on the basis of an end portion in an opposite side to the third semiconductor region of the first main surface to L , and a distance in the first direction of the boundary position on the basis of the end portion to X , X/L is not less than 0 and less than 0.5 .